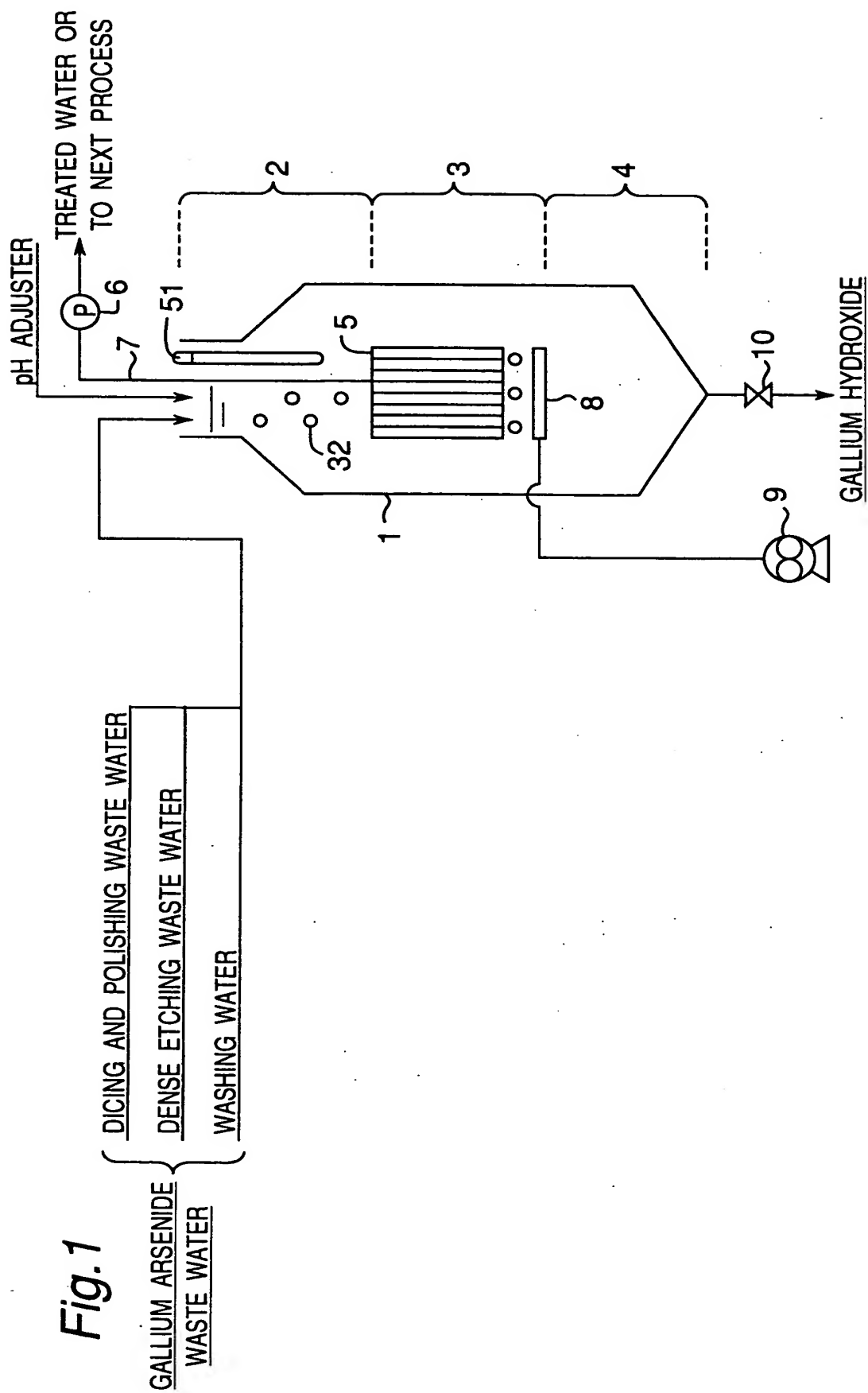


Fig. 1



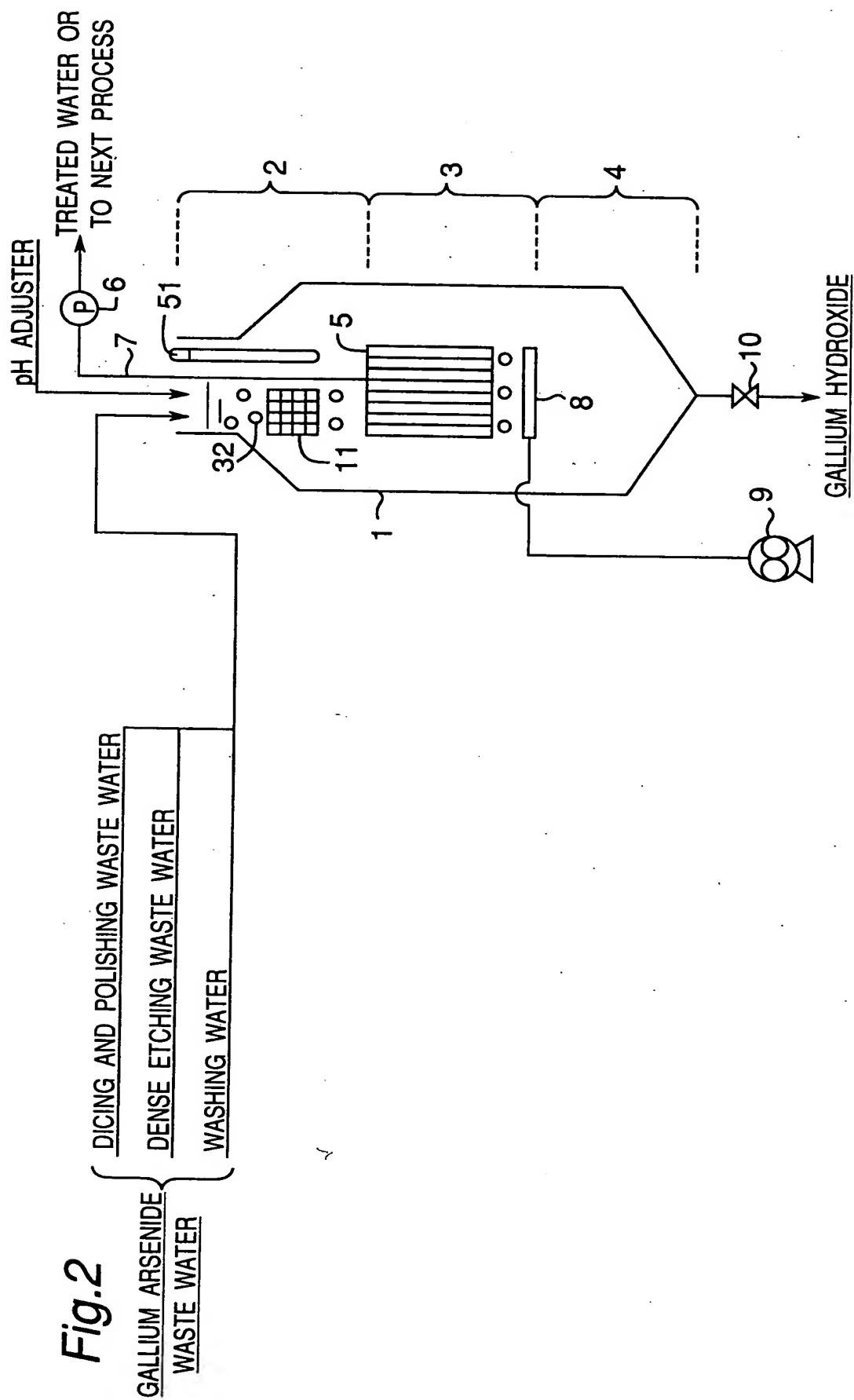


Fig.2

Fig.3

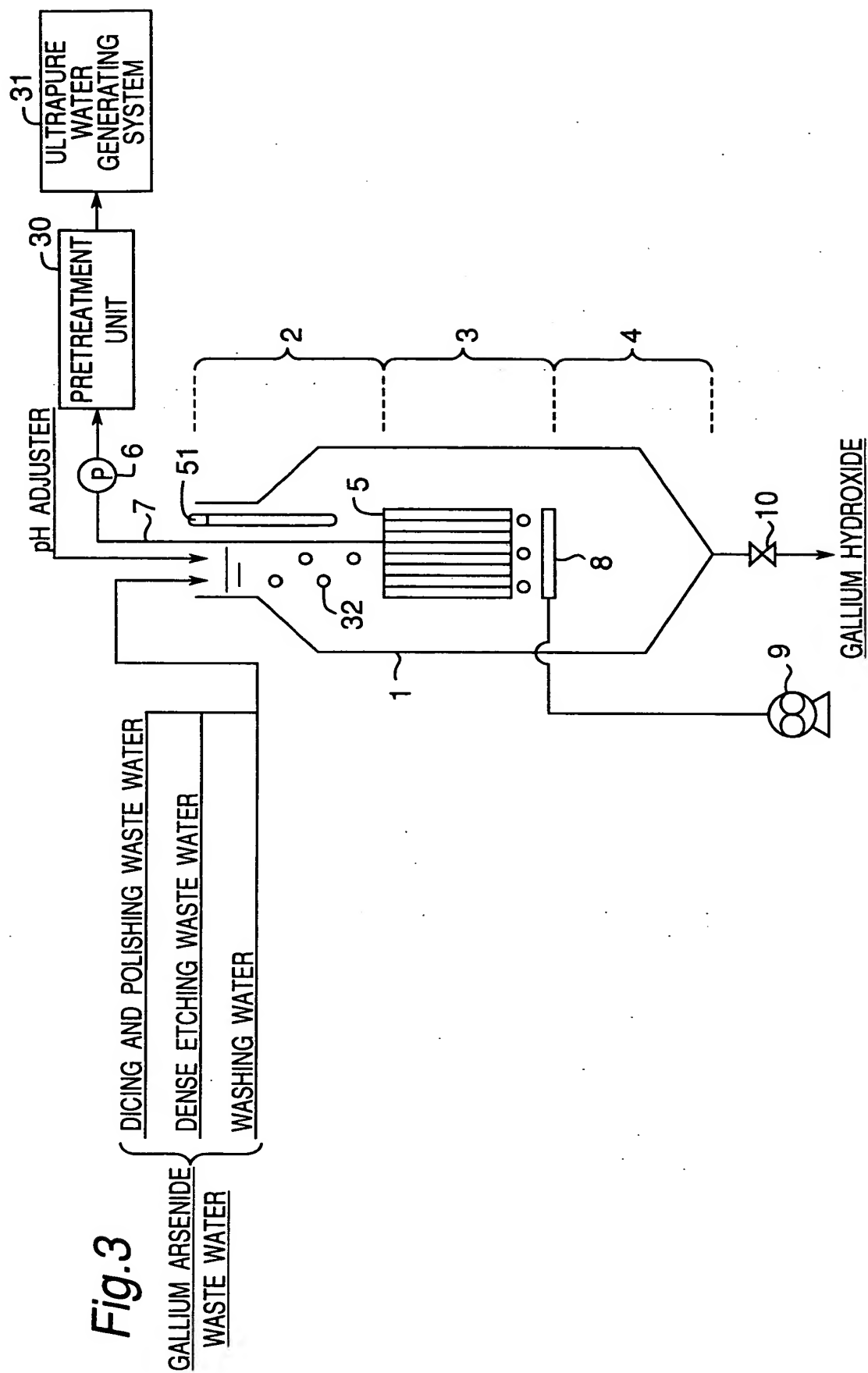


Fig.4

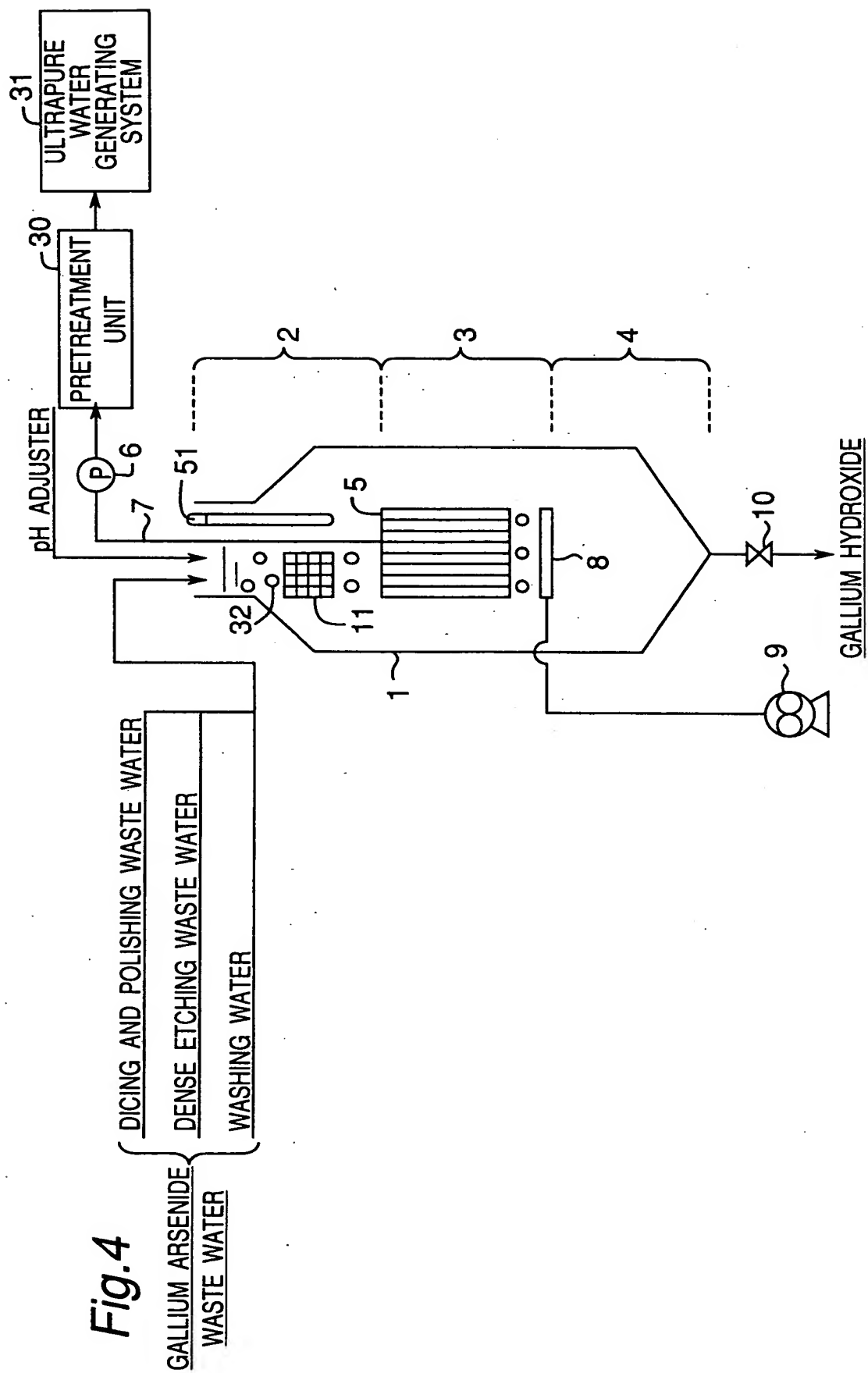


Fig.5

GALLIUM ARSENIDE
WASTE WATER

DICING AND POLISHING WASTE WATER
DENSE ETCHING WASTE WATER
WASHING WATER

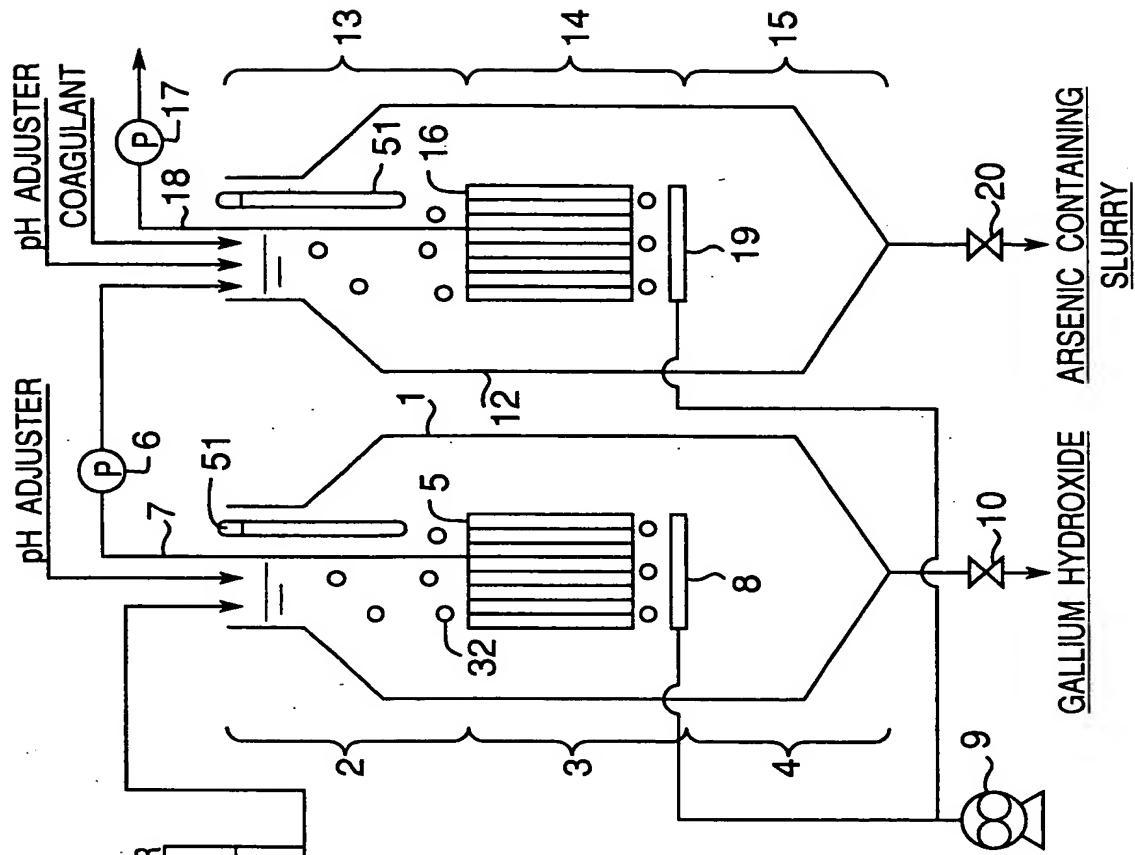


Fig.6

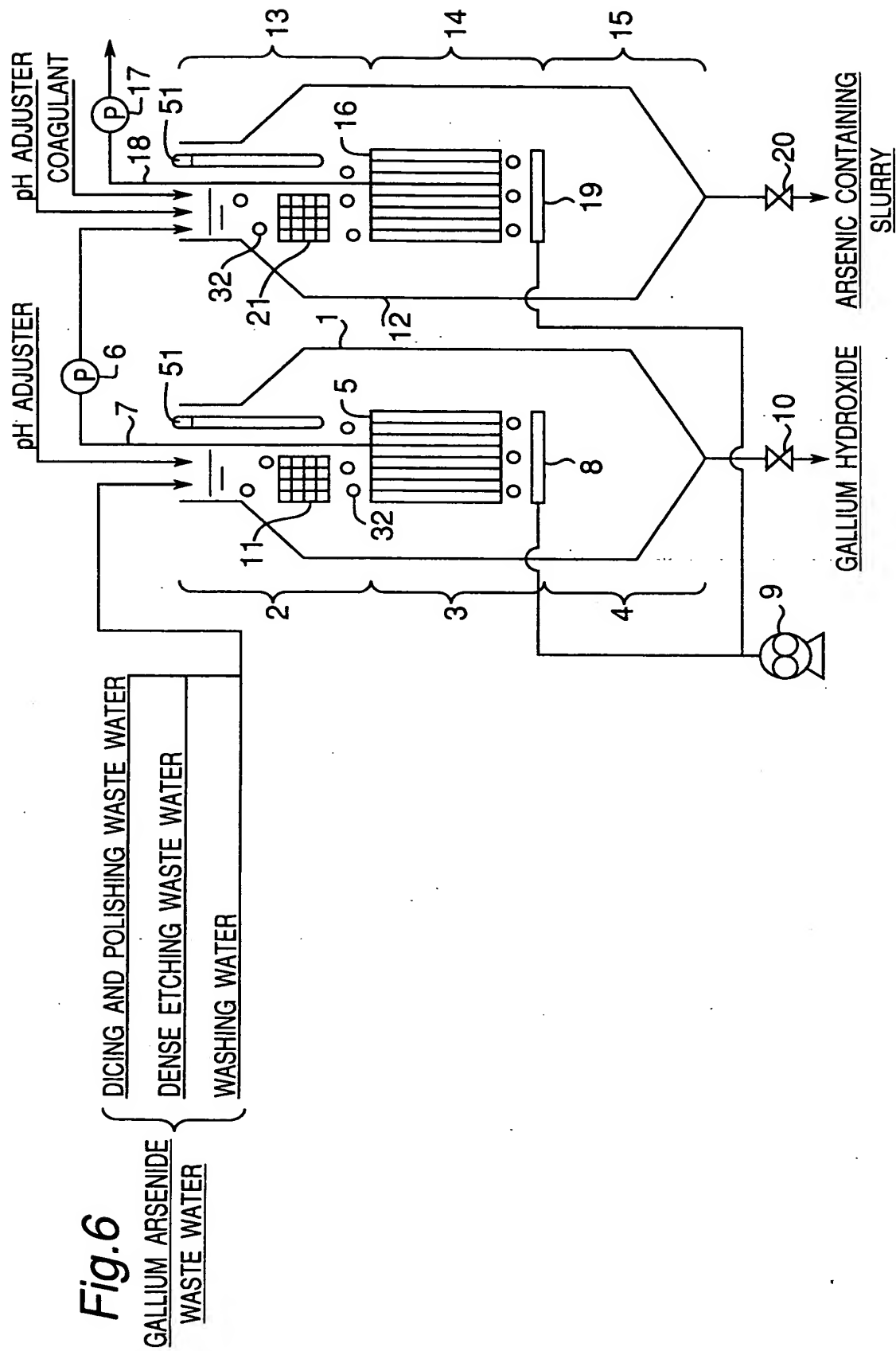


Fig. 7

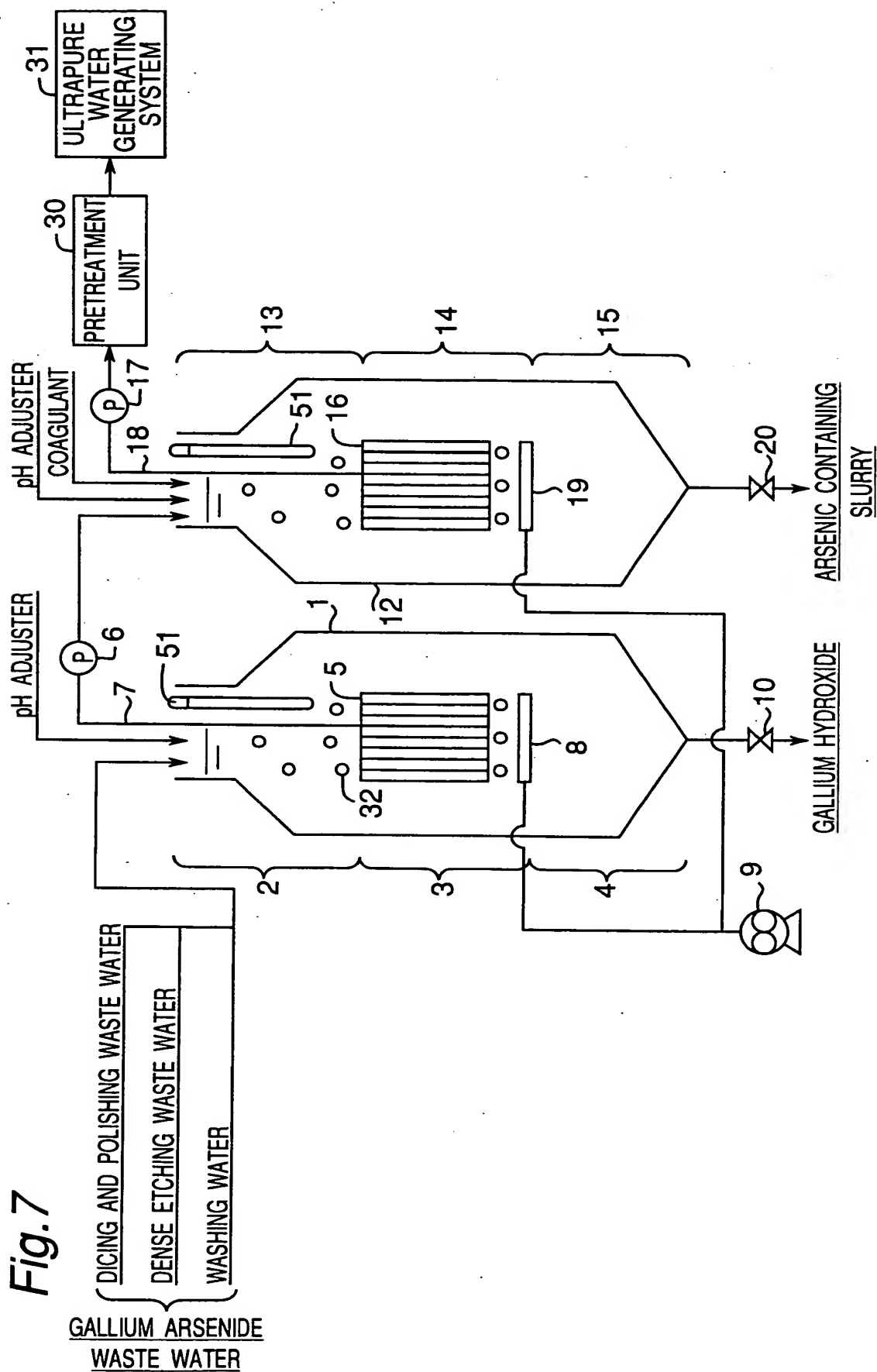


Fig.8

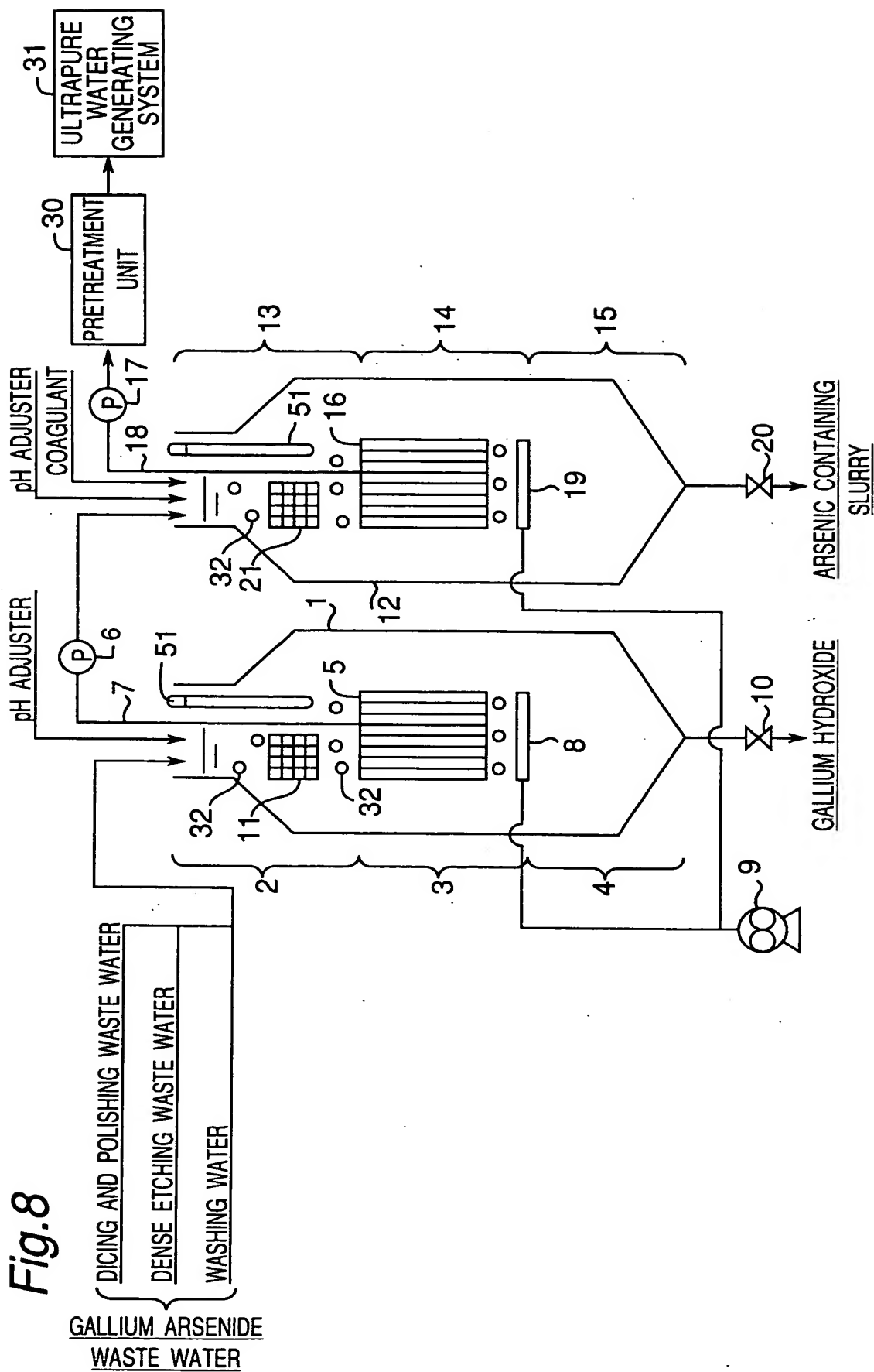


Fig.9

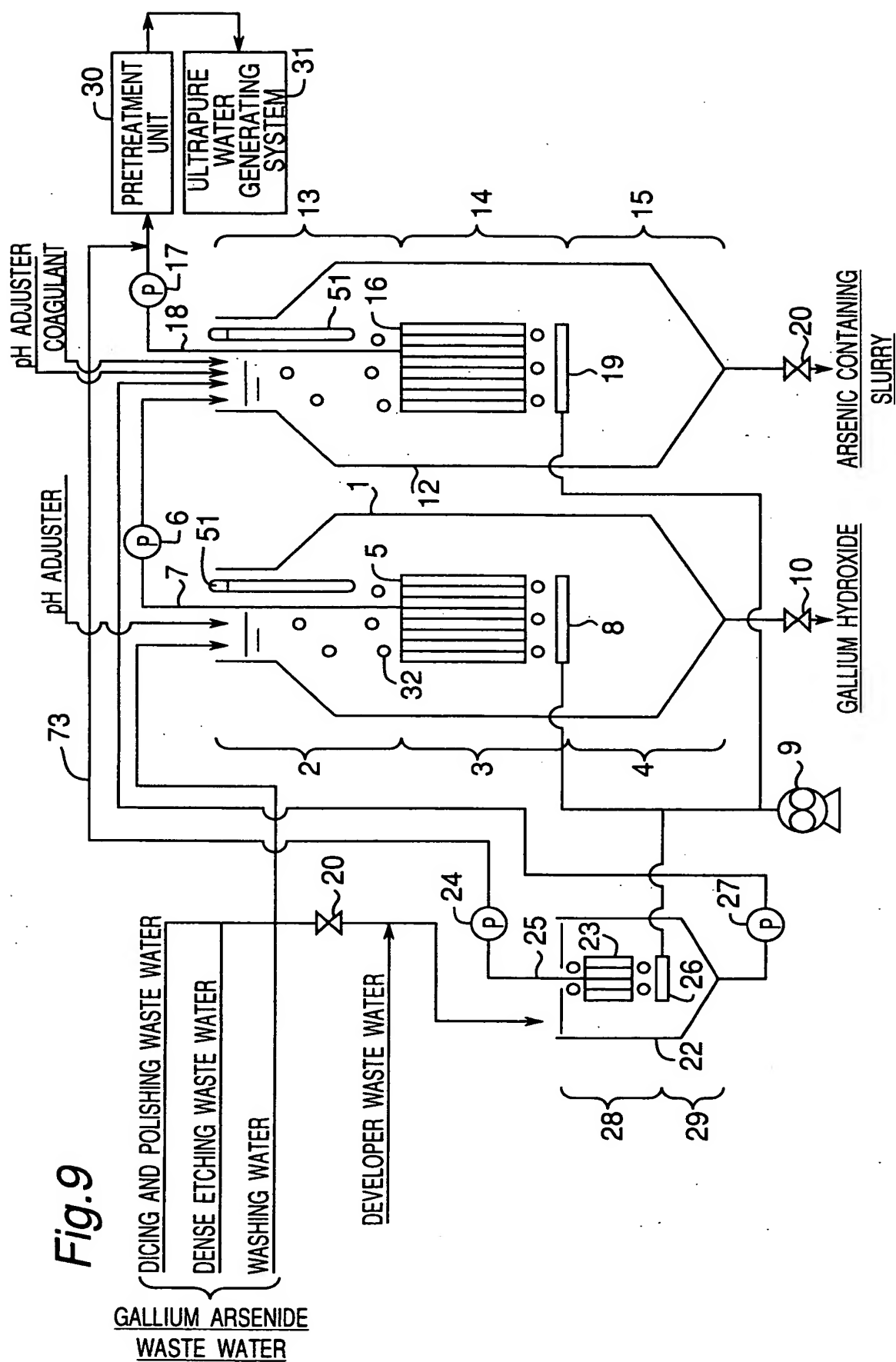


Fig. 10

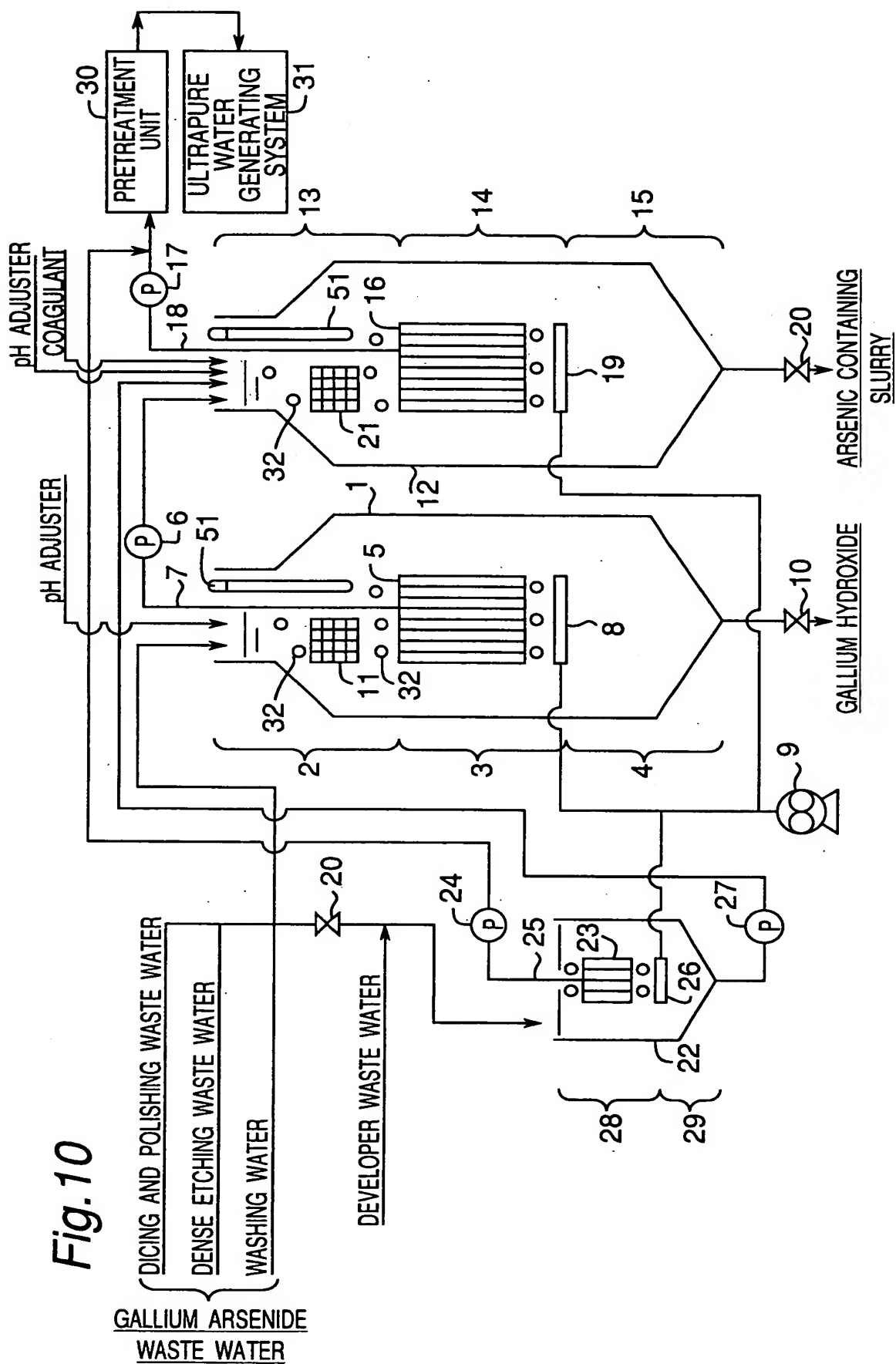


Fig. 11

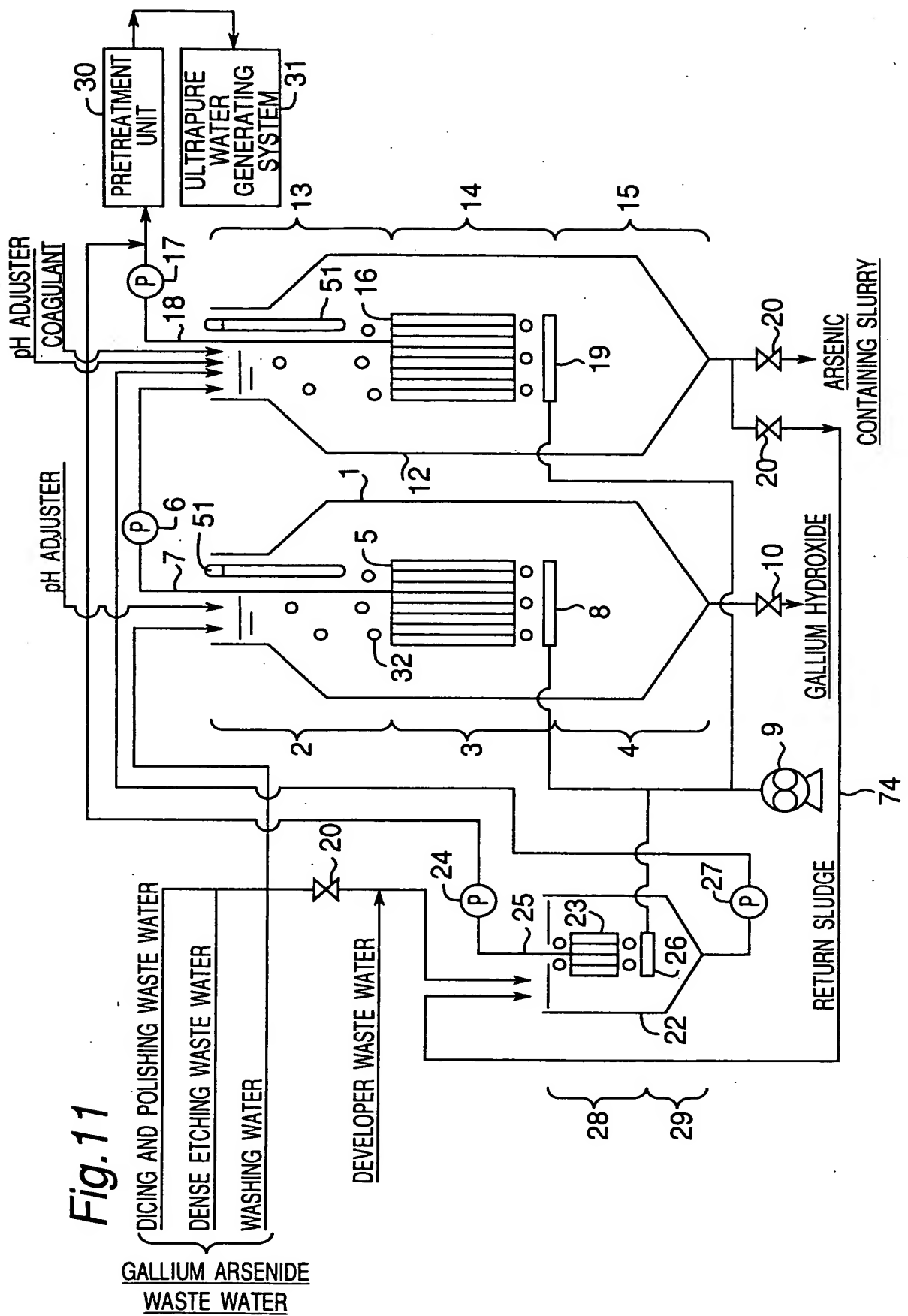


Fig. 12

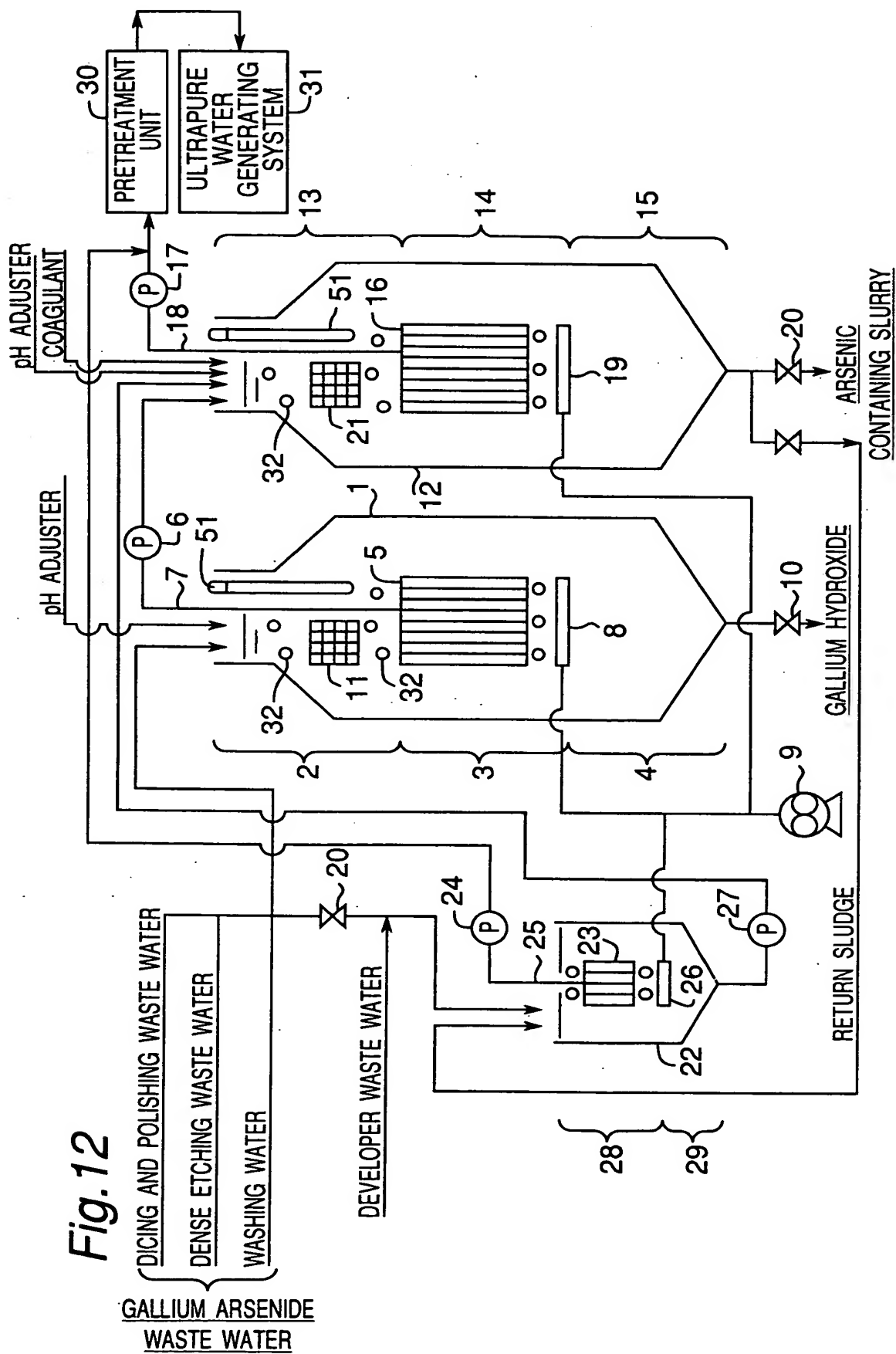


Fig. 13A

WHEN CONCENTRATIONS OF GALLIUM AND ARSENIC ARE NORMAL CONCENTRATIONS

[illegible]

Fig. 13B

WHEN CONCENTRATIONS OF GALLIUM AND ARSENIC ARE LOW CONCENTRATIONS

[illegible]

Fig. 14

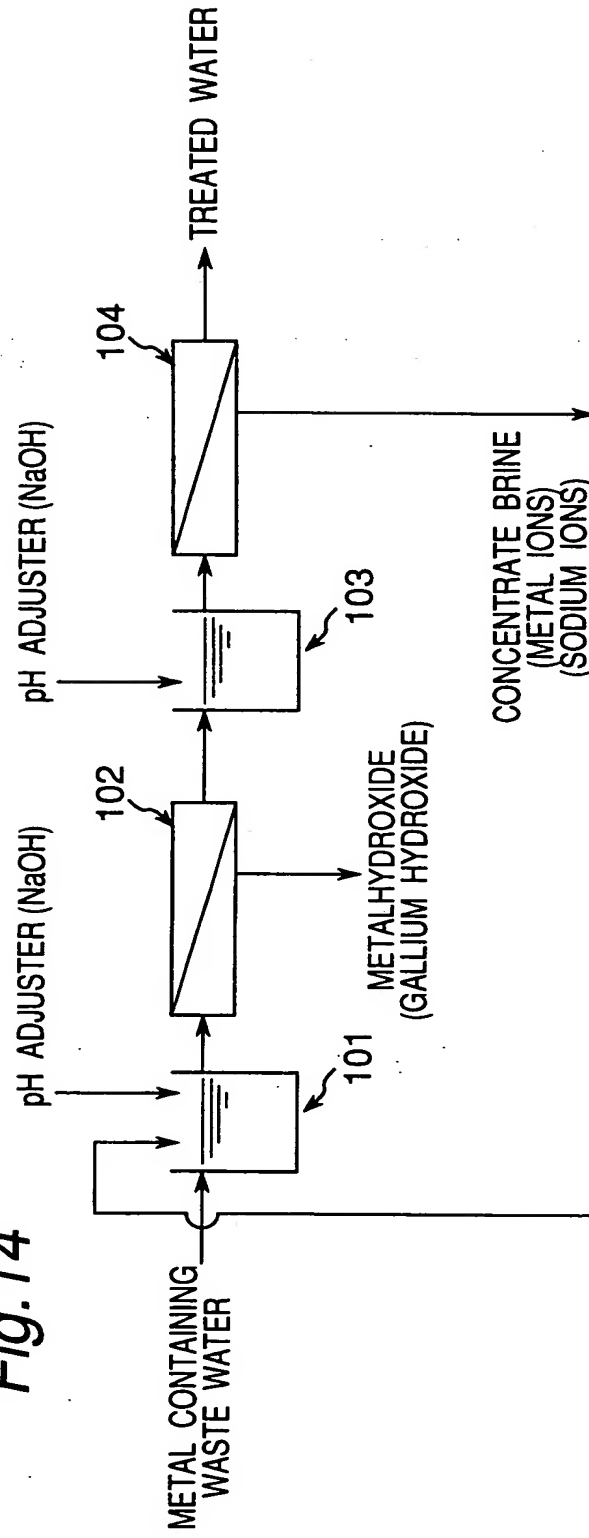


Fig. 15

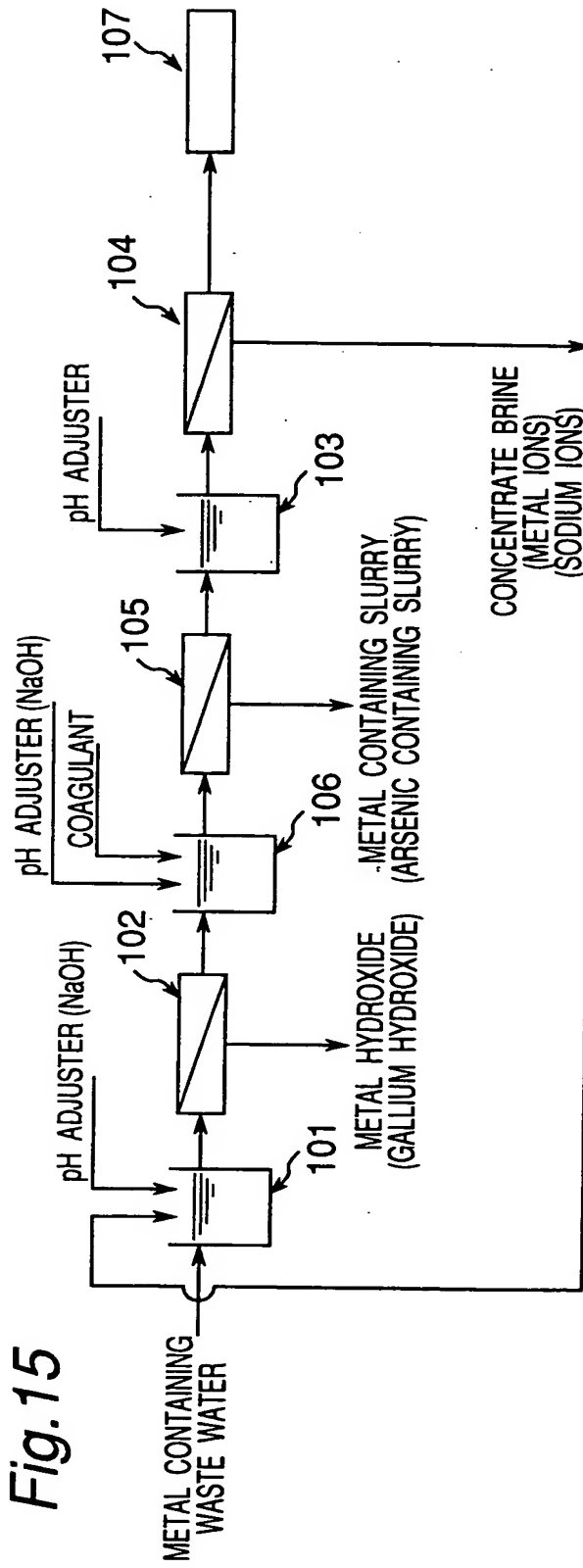


Fig. 16

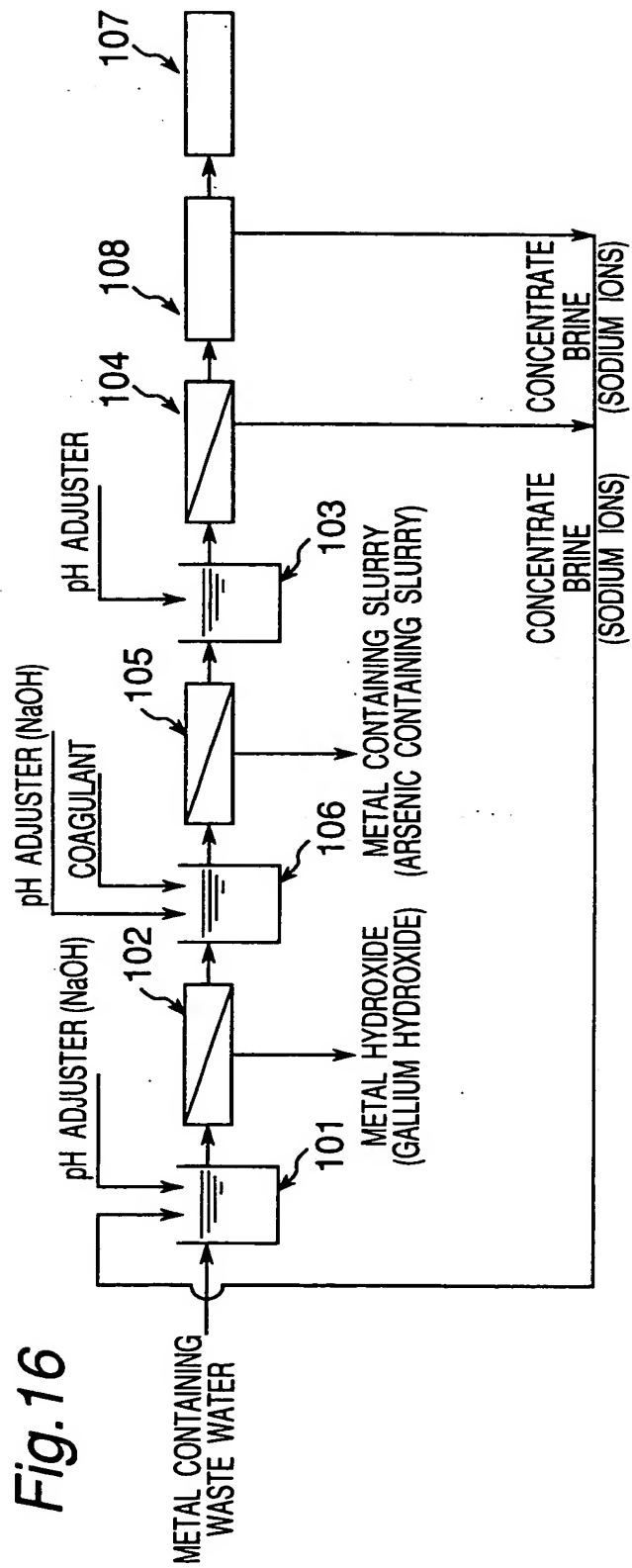


Fig. 17

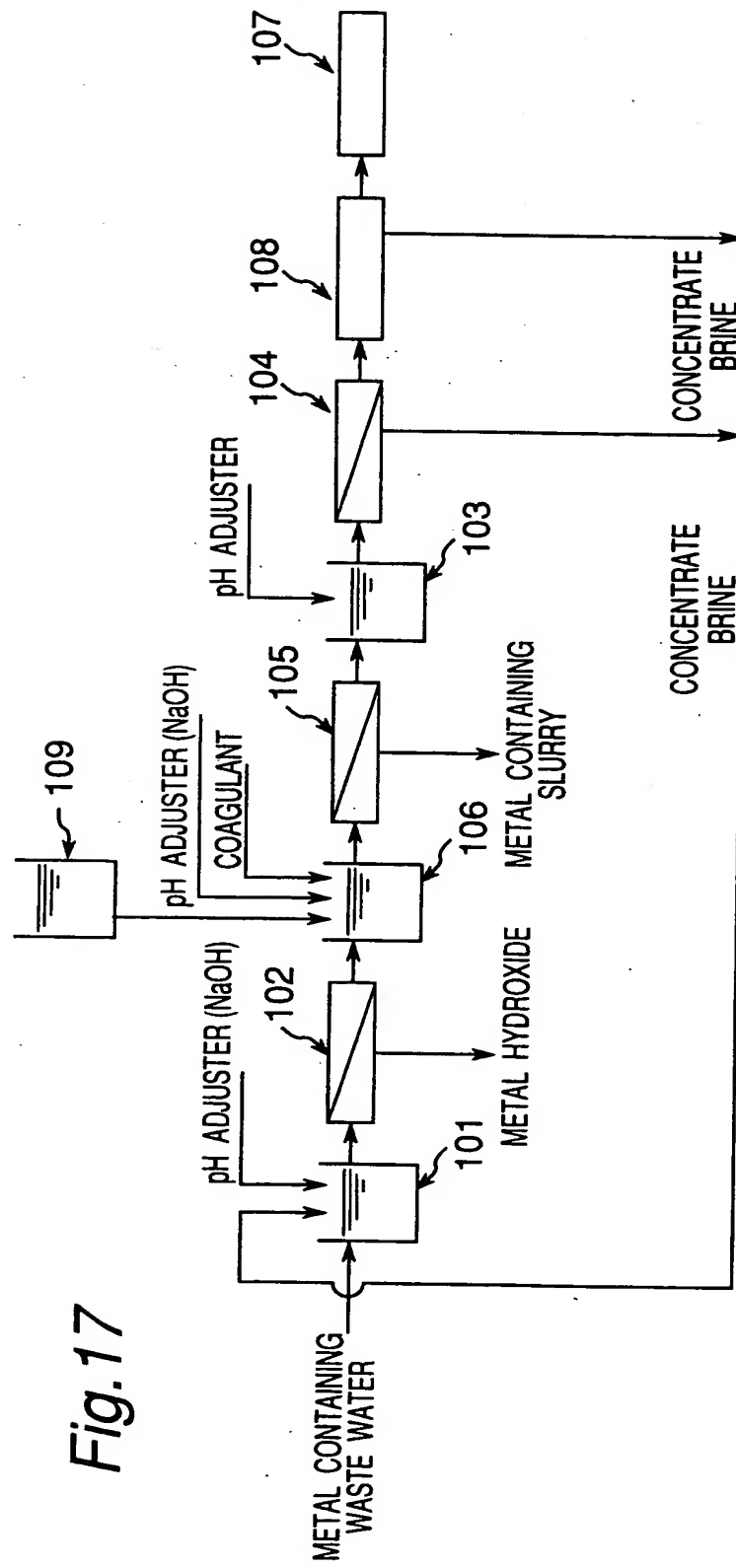


Fig.18

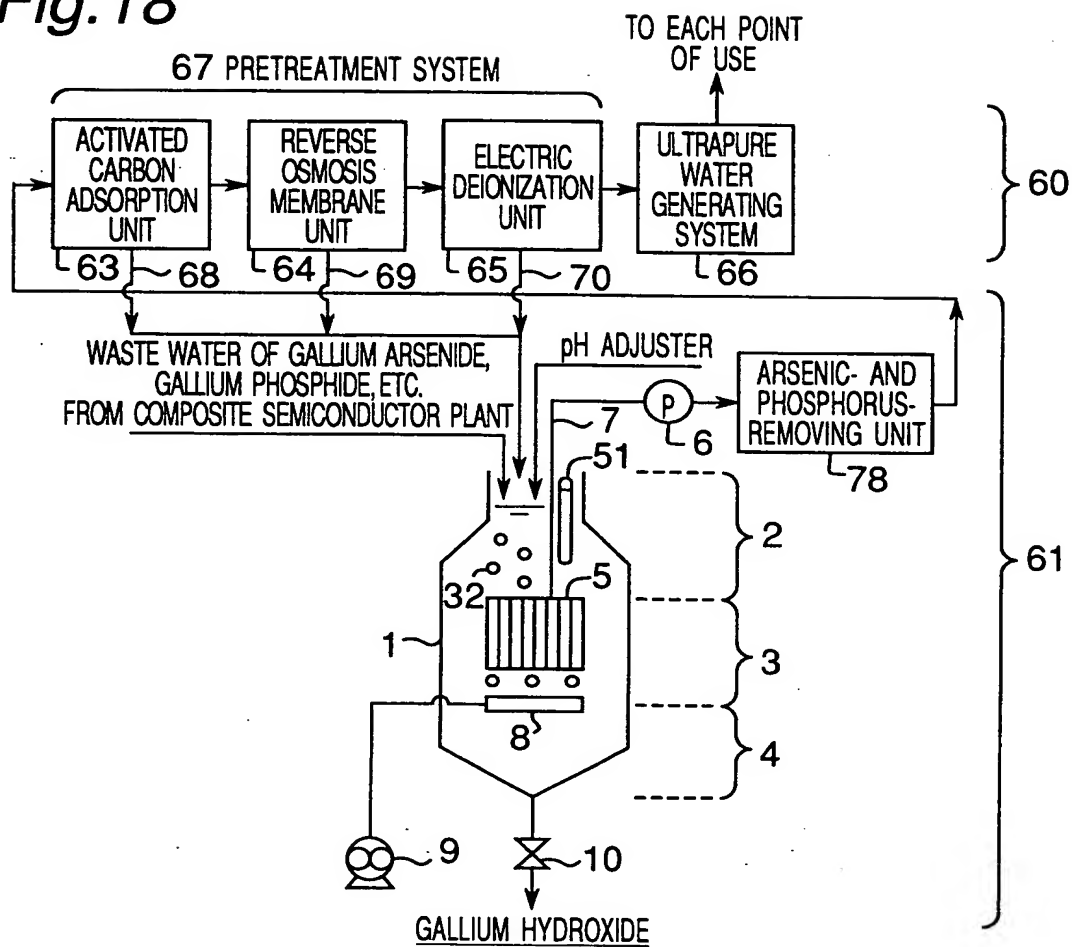


Fig. 19

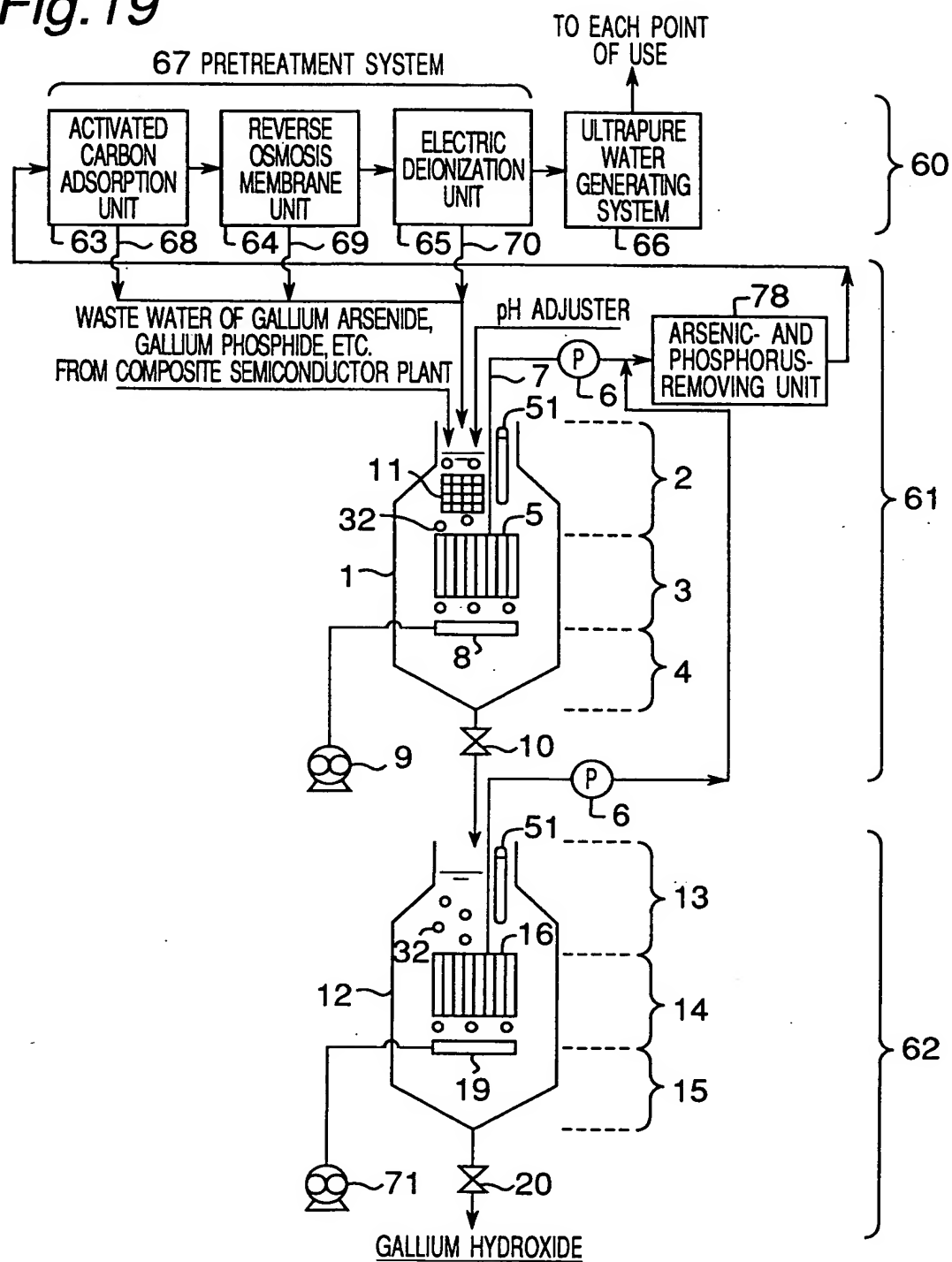


Fig.20

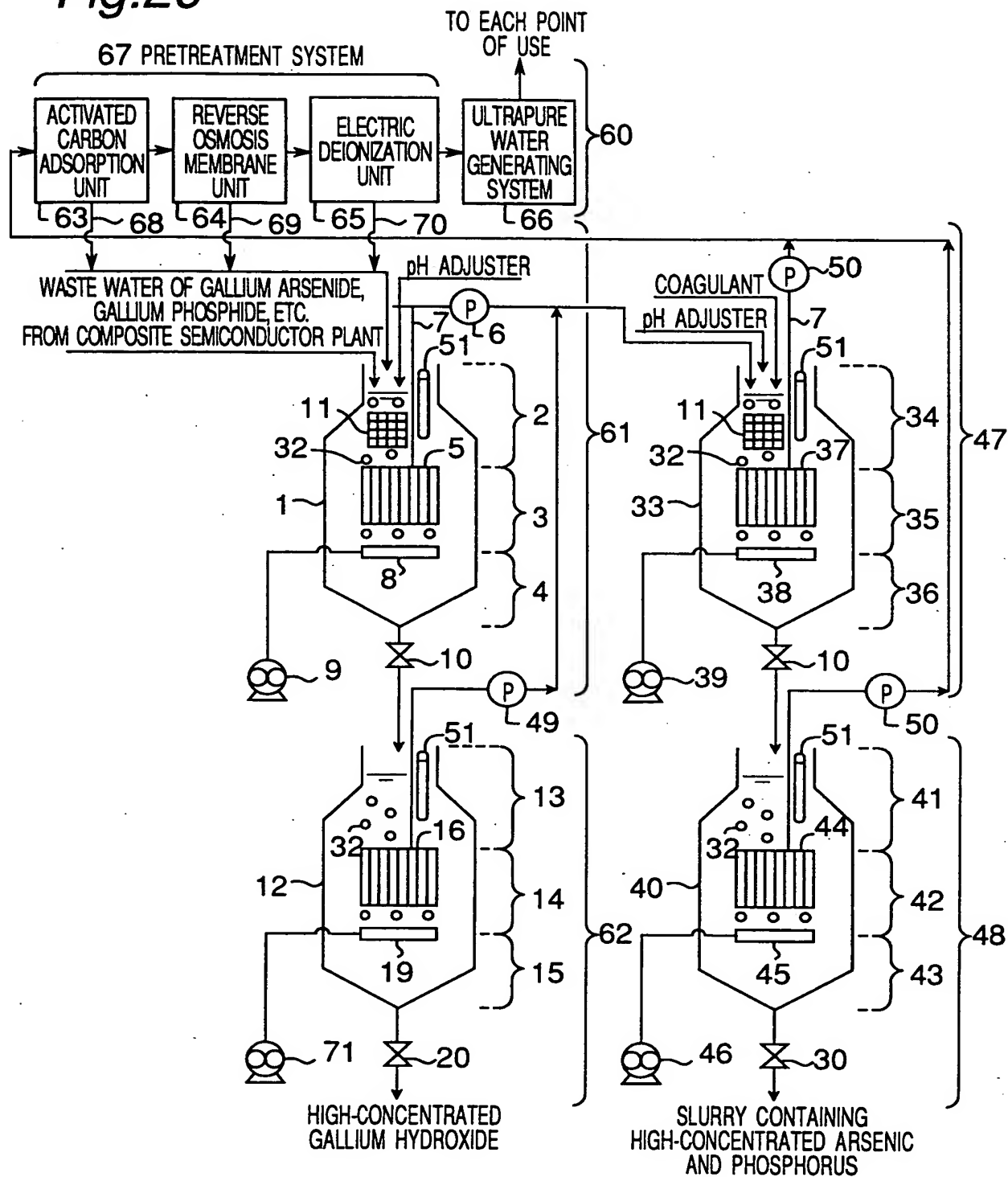


Fig.21

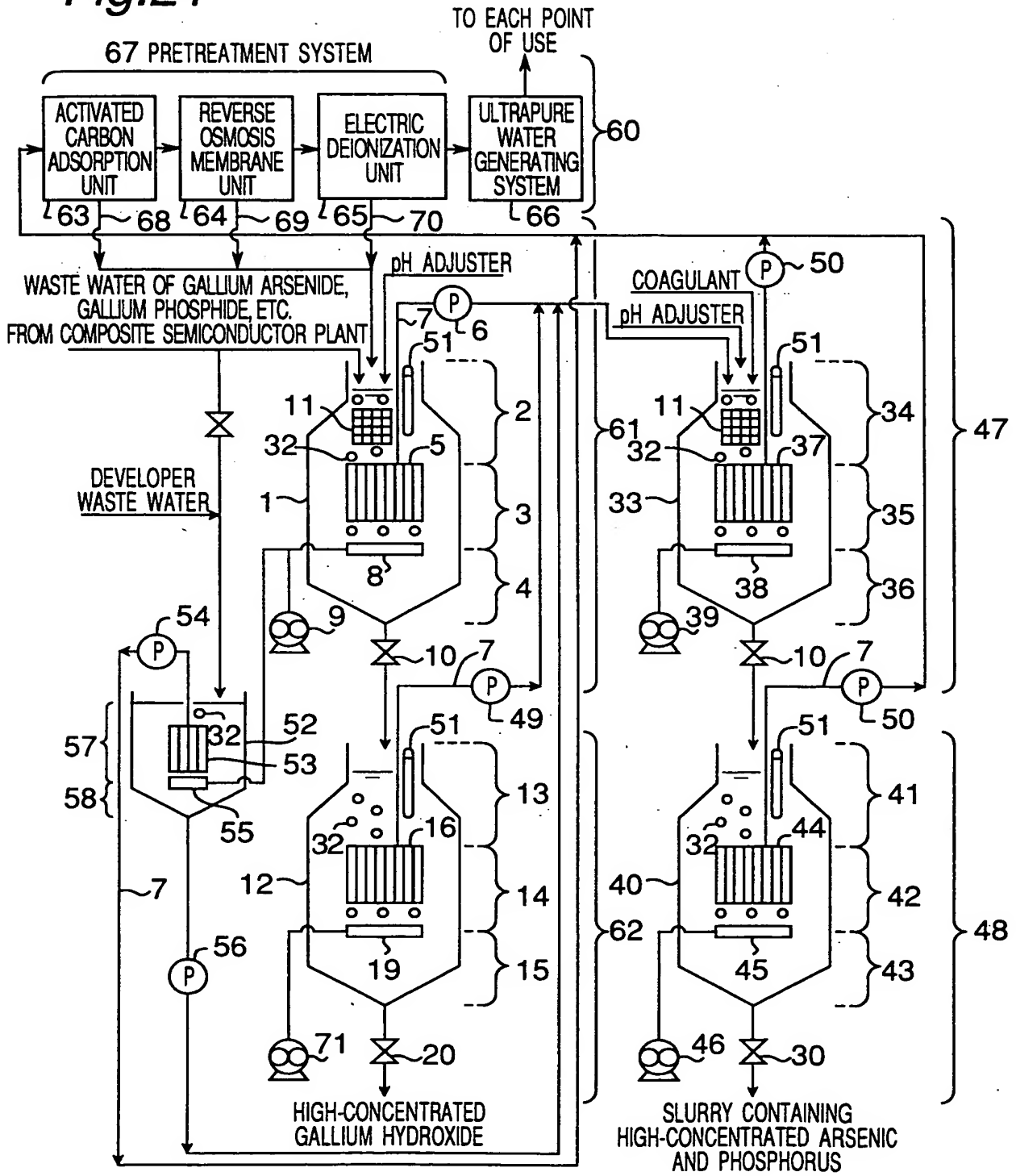


Fig.22

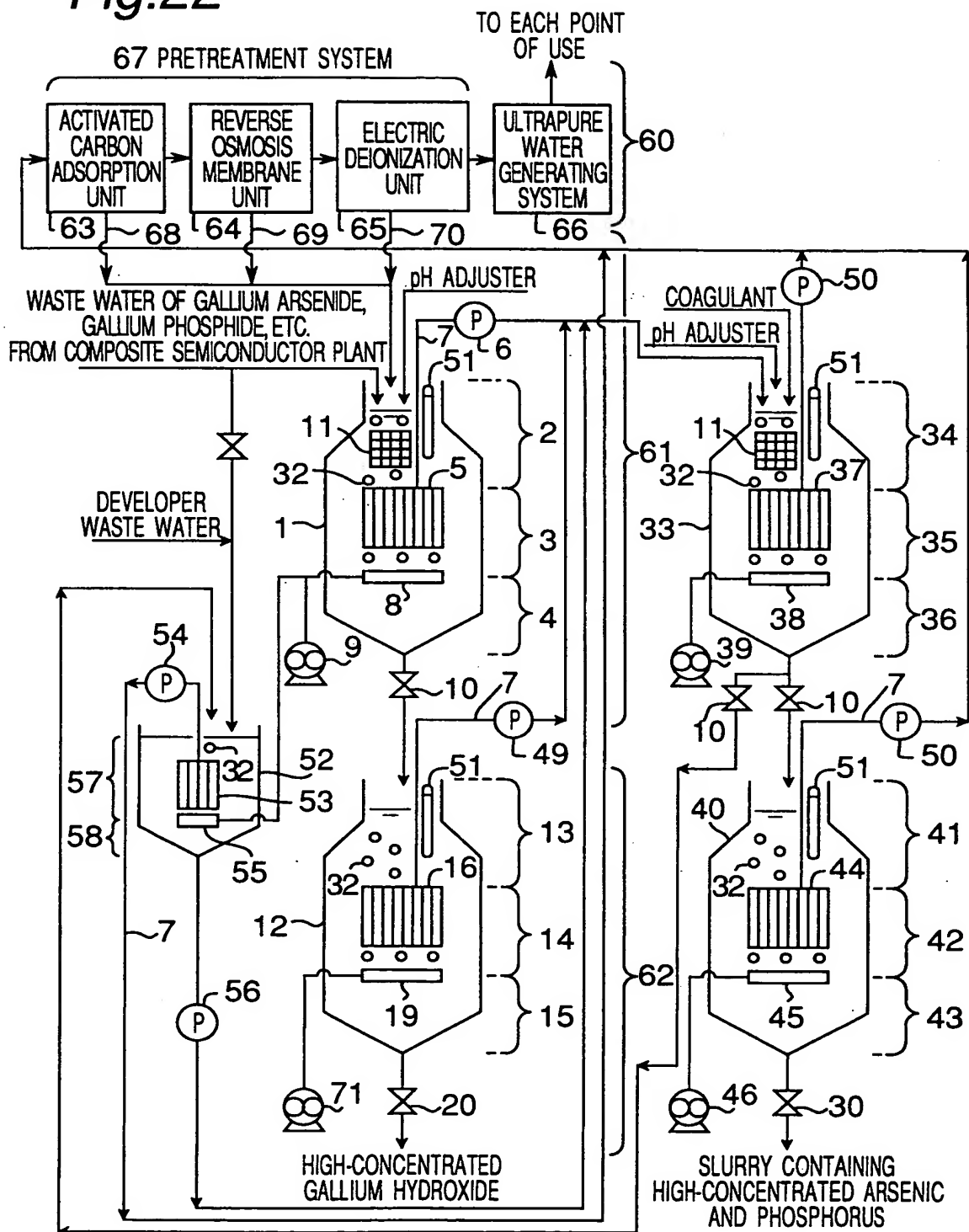


Fig.23

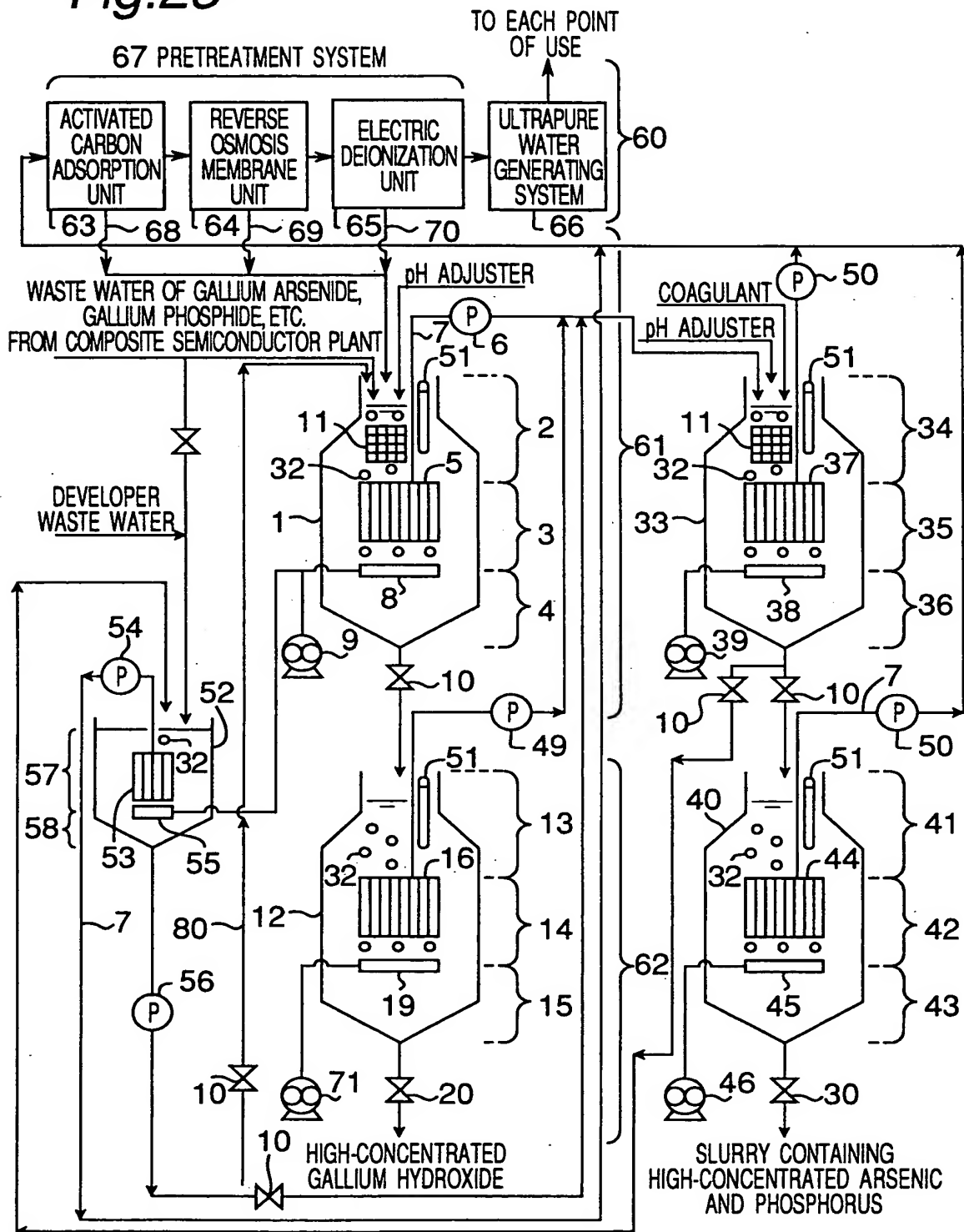


Fig.24

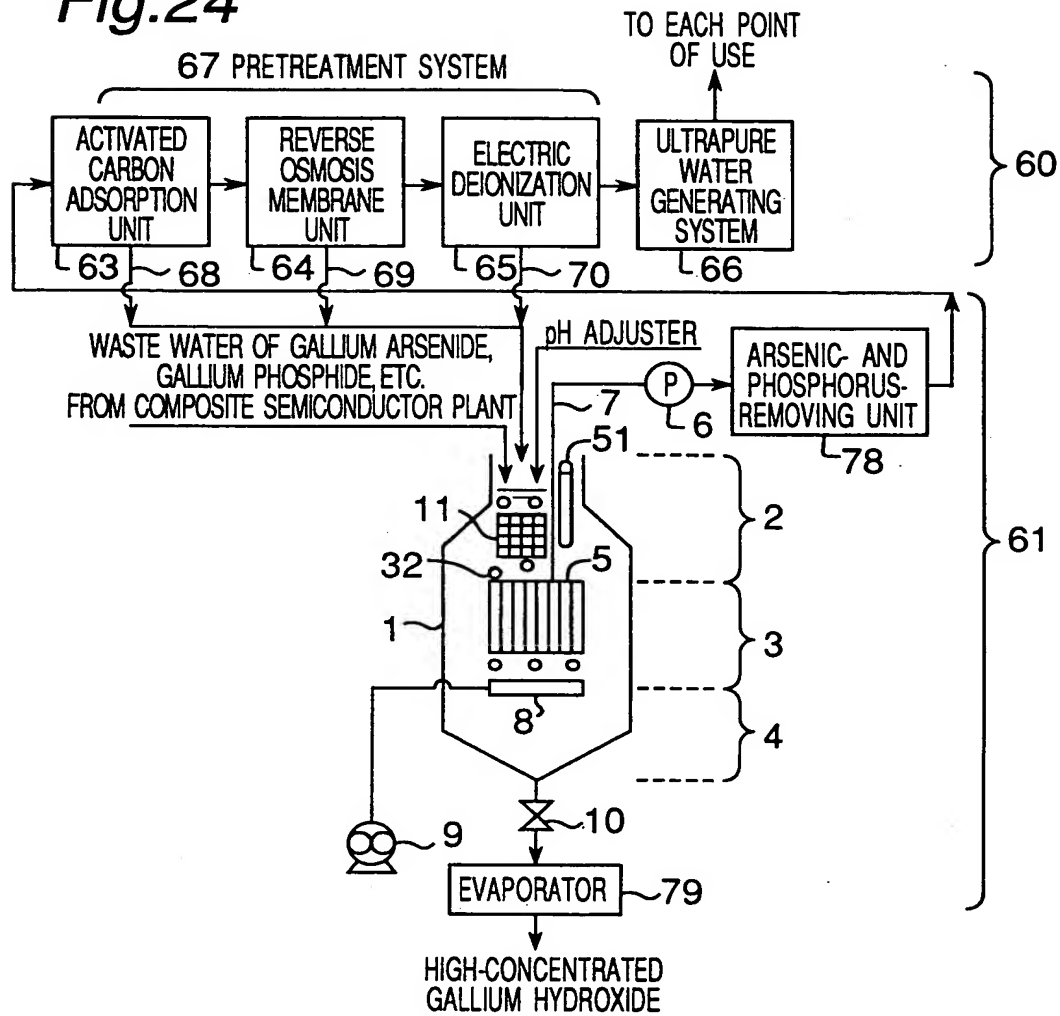


Fig.25

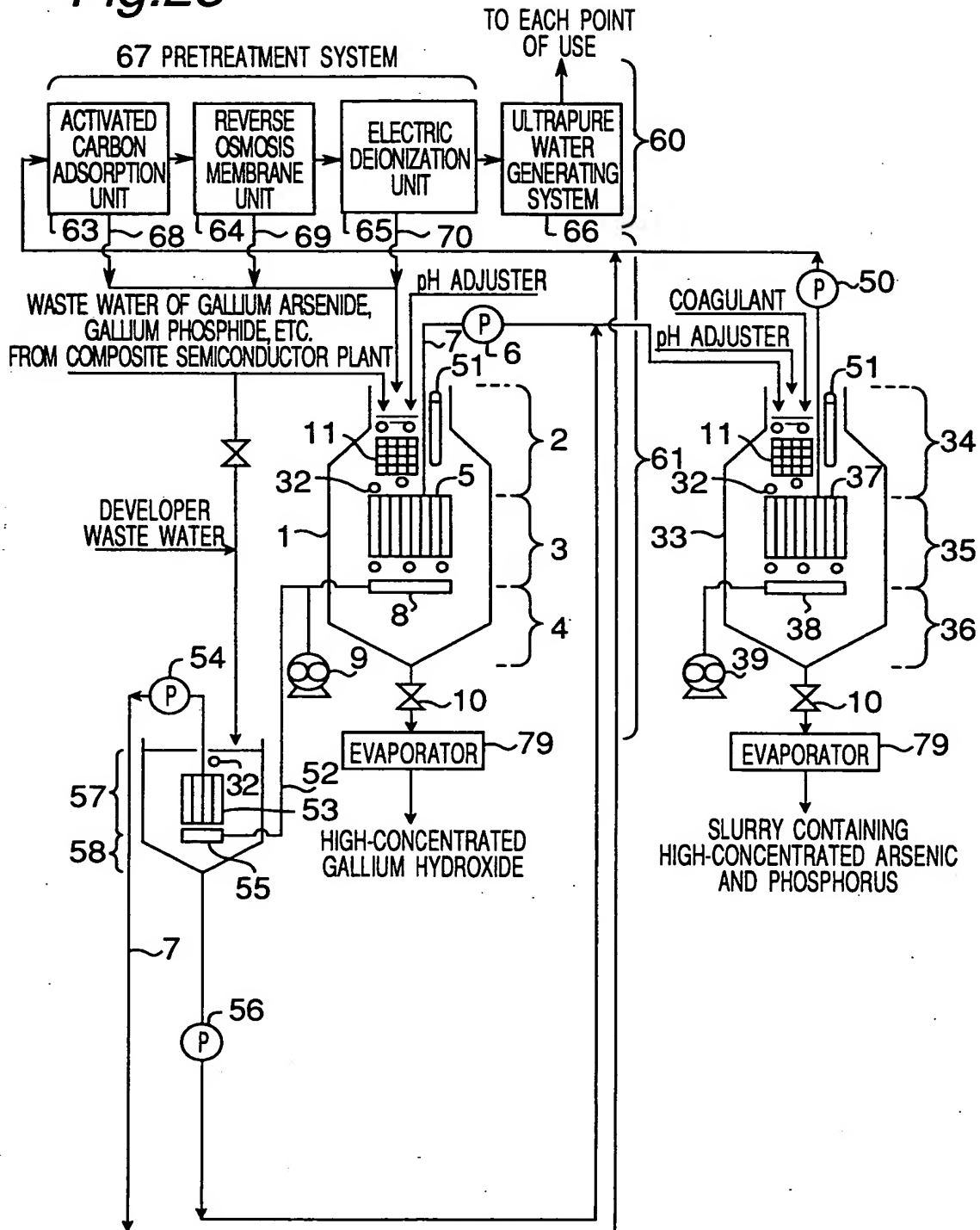


Fig.26

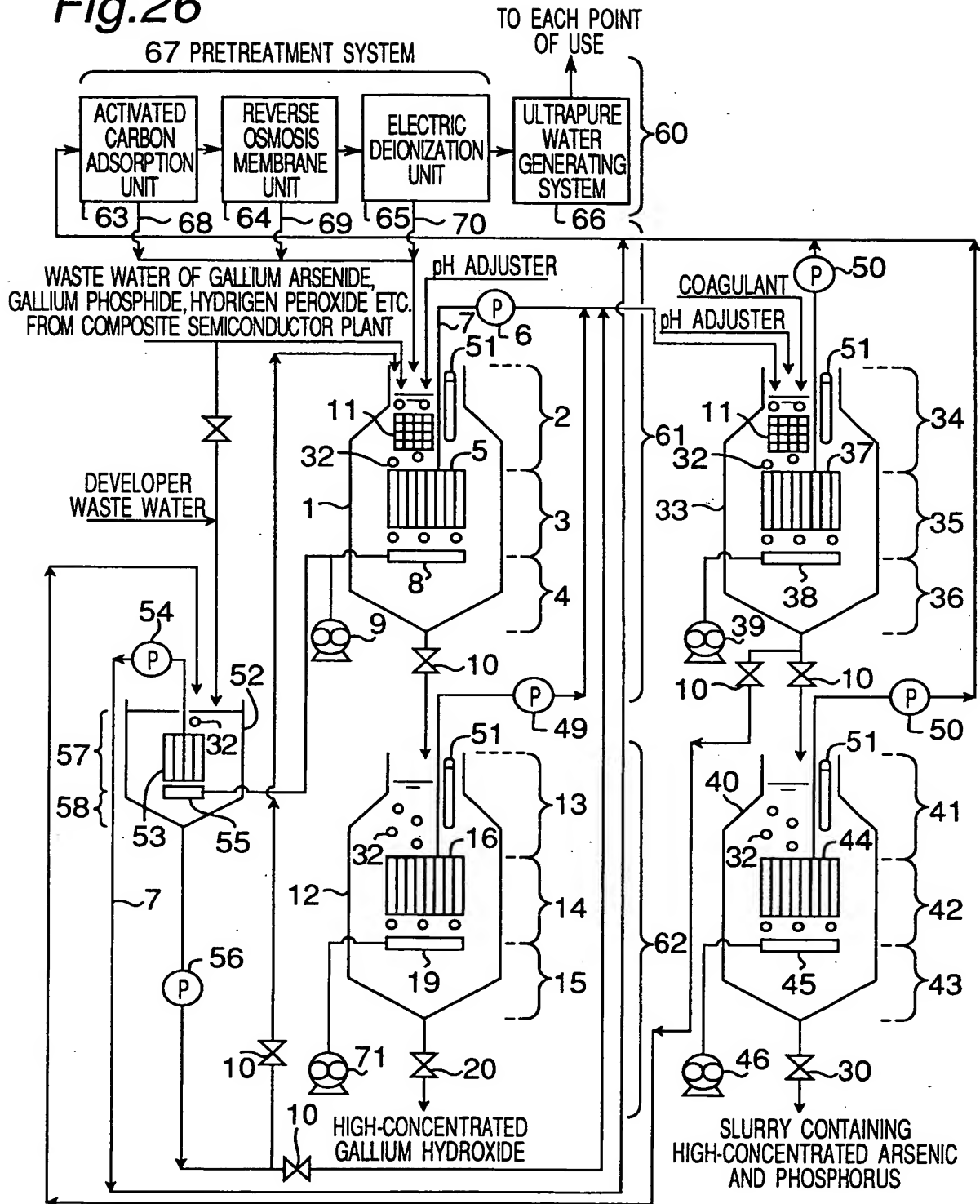


Fig.27A

WHEN CONCENTRATIONS OF GALLIUM AND ARSENIC ARE NORMAL CONCENTRATIONS

TANK NAME	RESIDENCE TIME	TIMING (RESIDENCE TIME)														
		1 HR.	2 HR.	3 HR.	4 HR.	5 HR.	6 HR.	7 HR.	8 HR.	9 HR.	10 HR.	11 HR.	12 HR.	13 HR.	14 HR.	15 HR.
SUBMERGED MEMBRANE SEPARATION TANK	1 HR.	—														
SECOND SUBMERGED MEMBRANE SEPARATION TANK	2 HR.		—	—												
THIRD SUBMERGED MEMBRANE SEPARATION TANK	4 HR.				—	—	—	—								
FOURTH SUBMERGED MEMBRANE SEPARATION TANK	4 HR.								—	—	—	—				

Fig.27B

WHEN CONCENTRATIONS OF GALLIUM AND ARSENIC ARE LOW CONCENTRATIONS

TANK NAME	RESIDENCE TIME	TIMING (RESIDENCE TIME)														
		1 HR.	2 HR.	3 HR.	4 HR.	5 HR.	6 HR.	7 HR.	8 HR.	9 HR.	10 HR.	11 HR.	12 HR.	13 HR.	14 HR.	15 HR.
SUBMERGED MEMBRANE SEPARATION TANK	1 HR.	—														
SECOND SUBMERGED MEMBRANE SEPARATION TANK	2 HR.		—	—												
THIRD SUBMERGED MEMBRANE SEPARATION TANK	3 HR.				—	—	—									
FOURTH SUBMERGED MEMBRANE SEPARATION TANK	3 HR.							—	—	—						

Fig. 28A

WHEN CONCENTRATIONS OF GALLIUM AND ARSENIC ARE NORMAL CONCENTRATIONS

[illegible]

Fig. 28B

WHEN CONCENTRATIONS OF GALLIUM AND ARSENIC ARE LOW CONCENTRATIONS

[illegible]

Fig.29

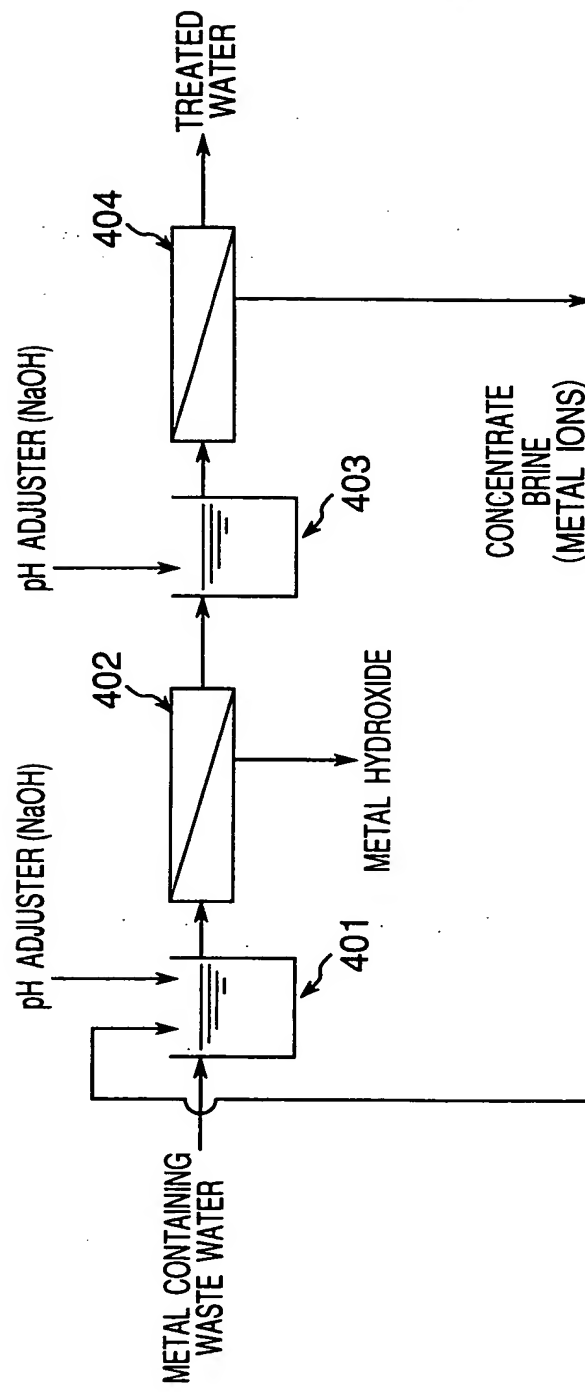


Fig.30

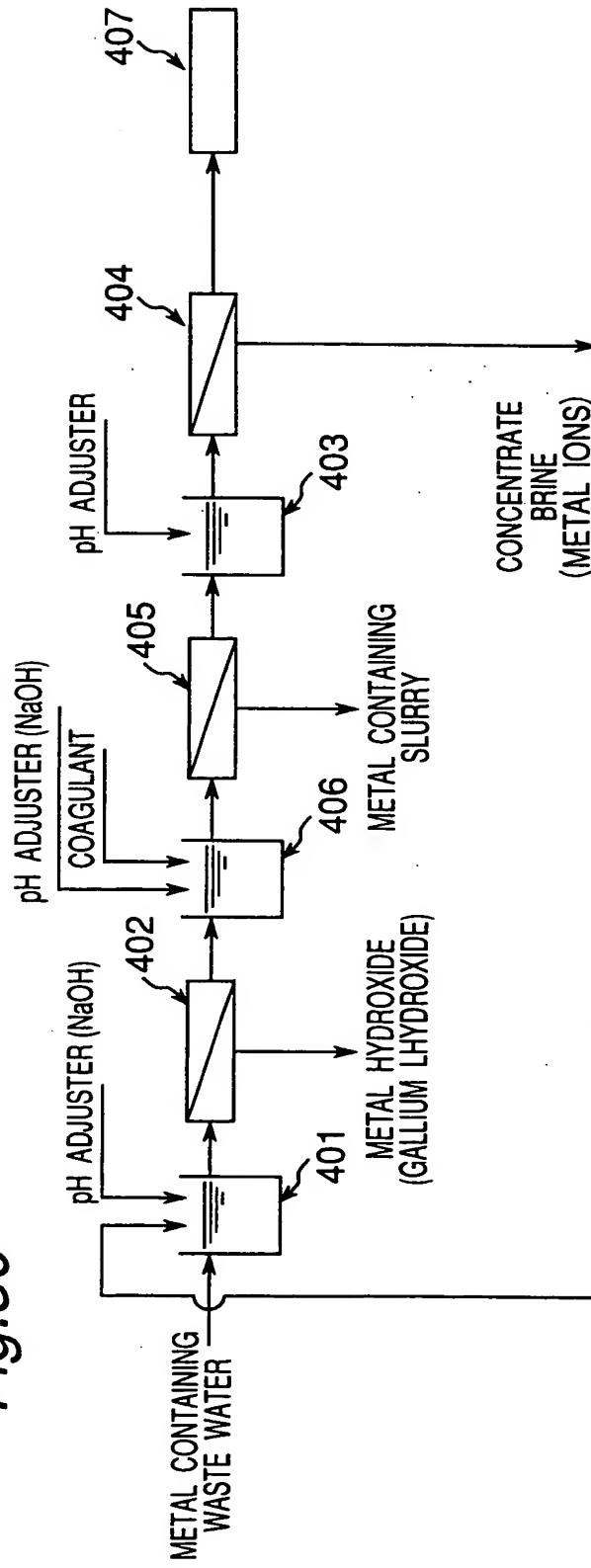


Fig.31

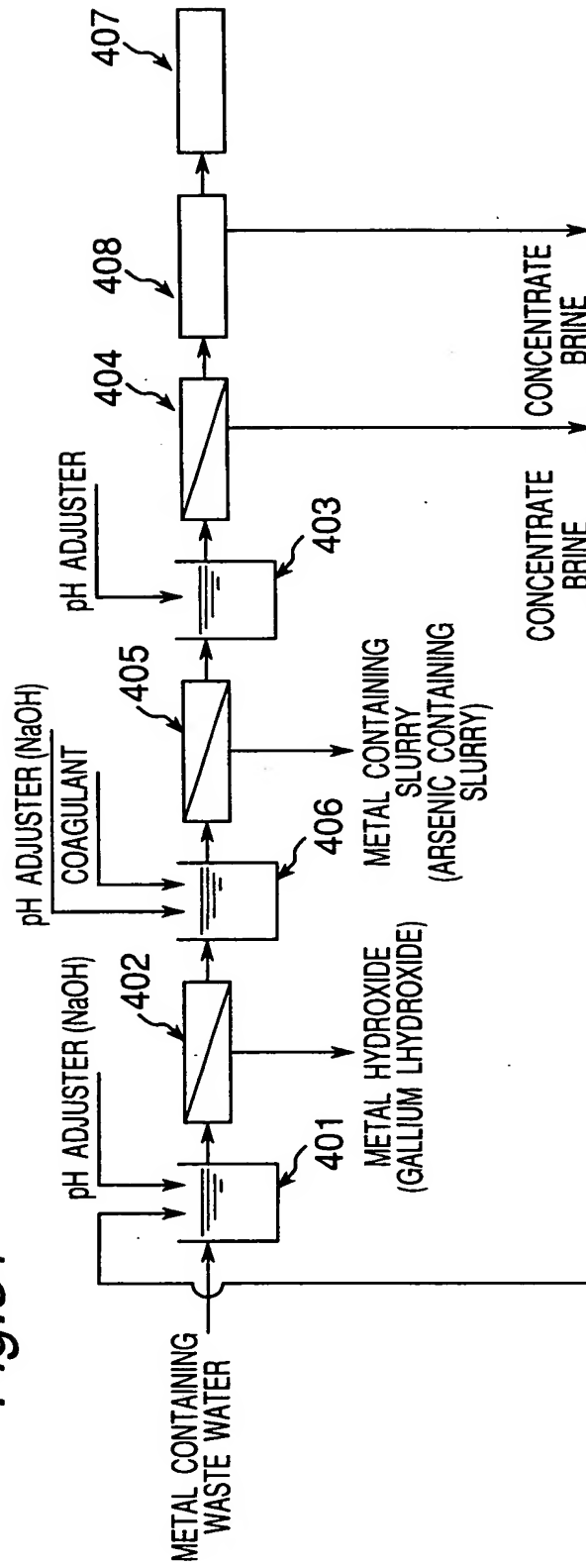


Fig.32

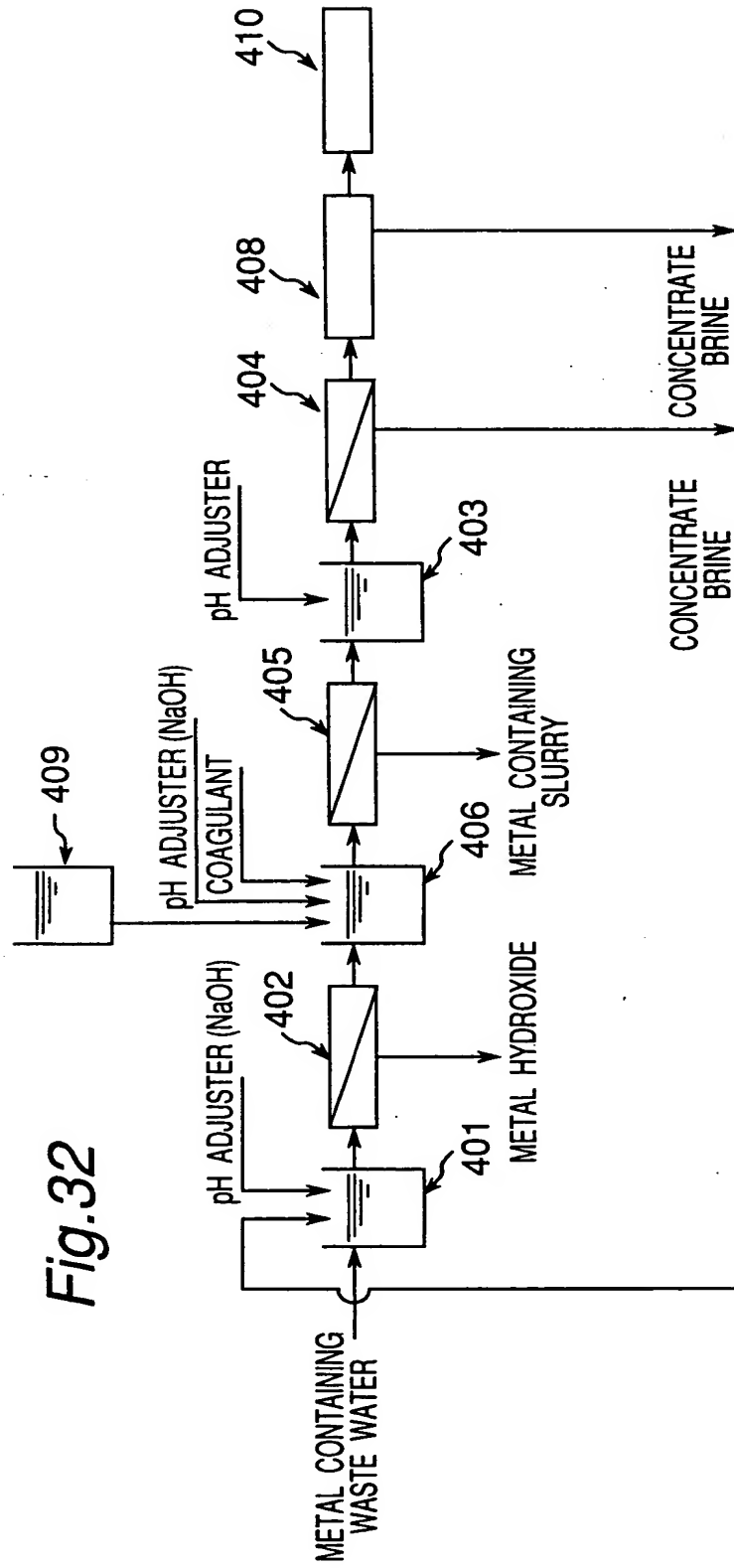


Fig.33

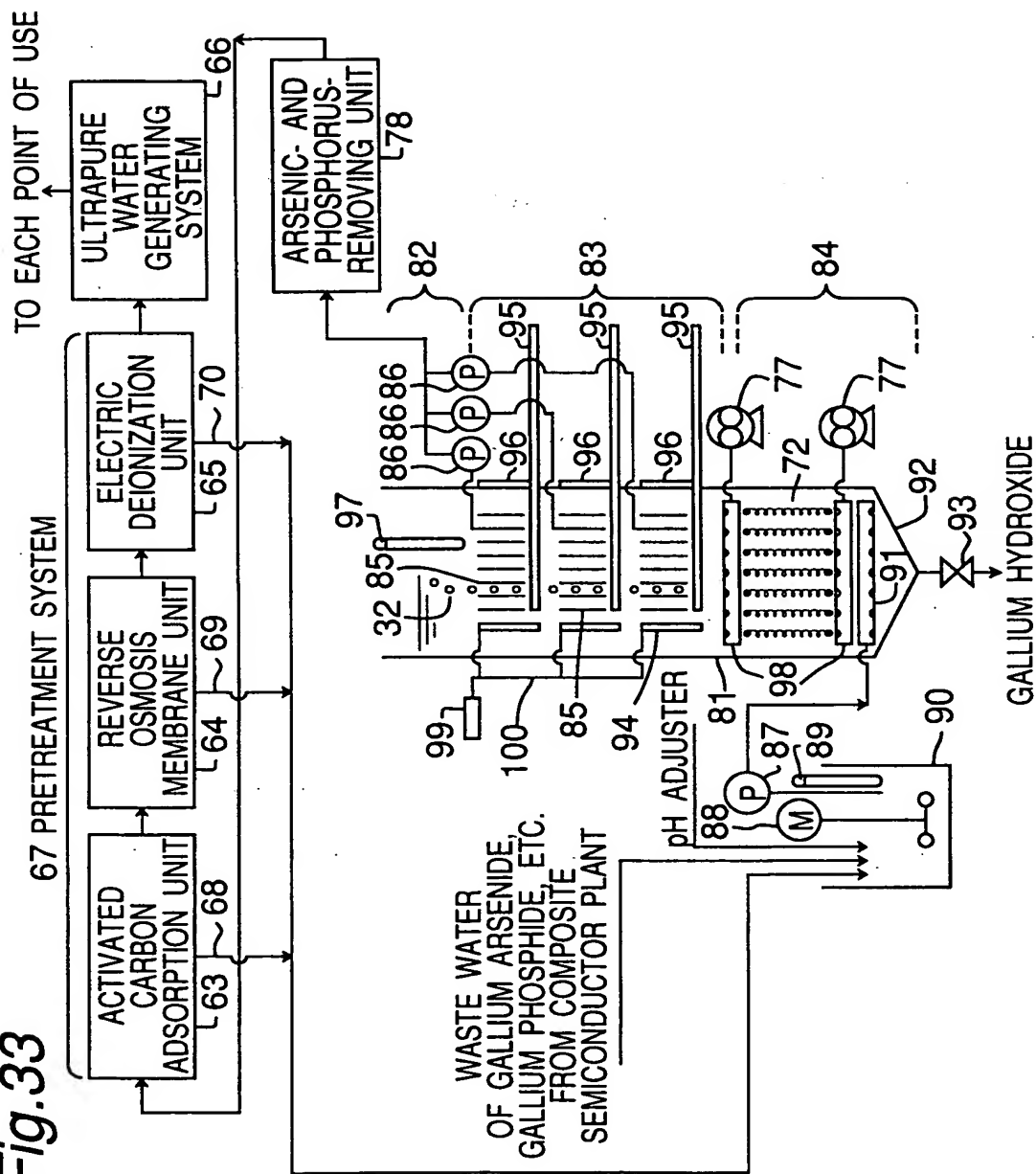


Fig.34

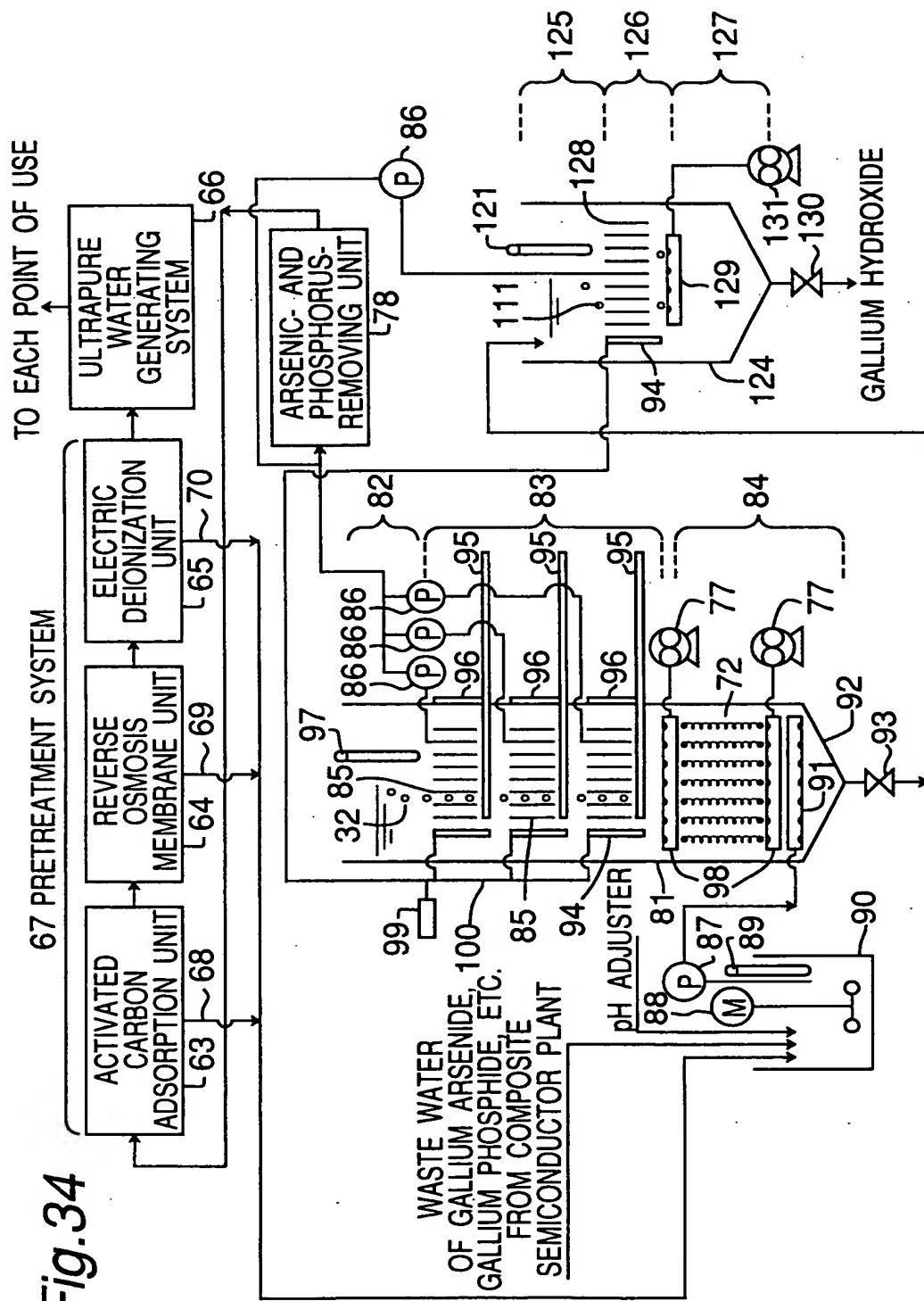
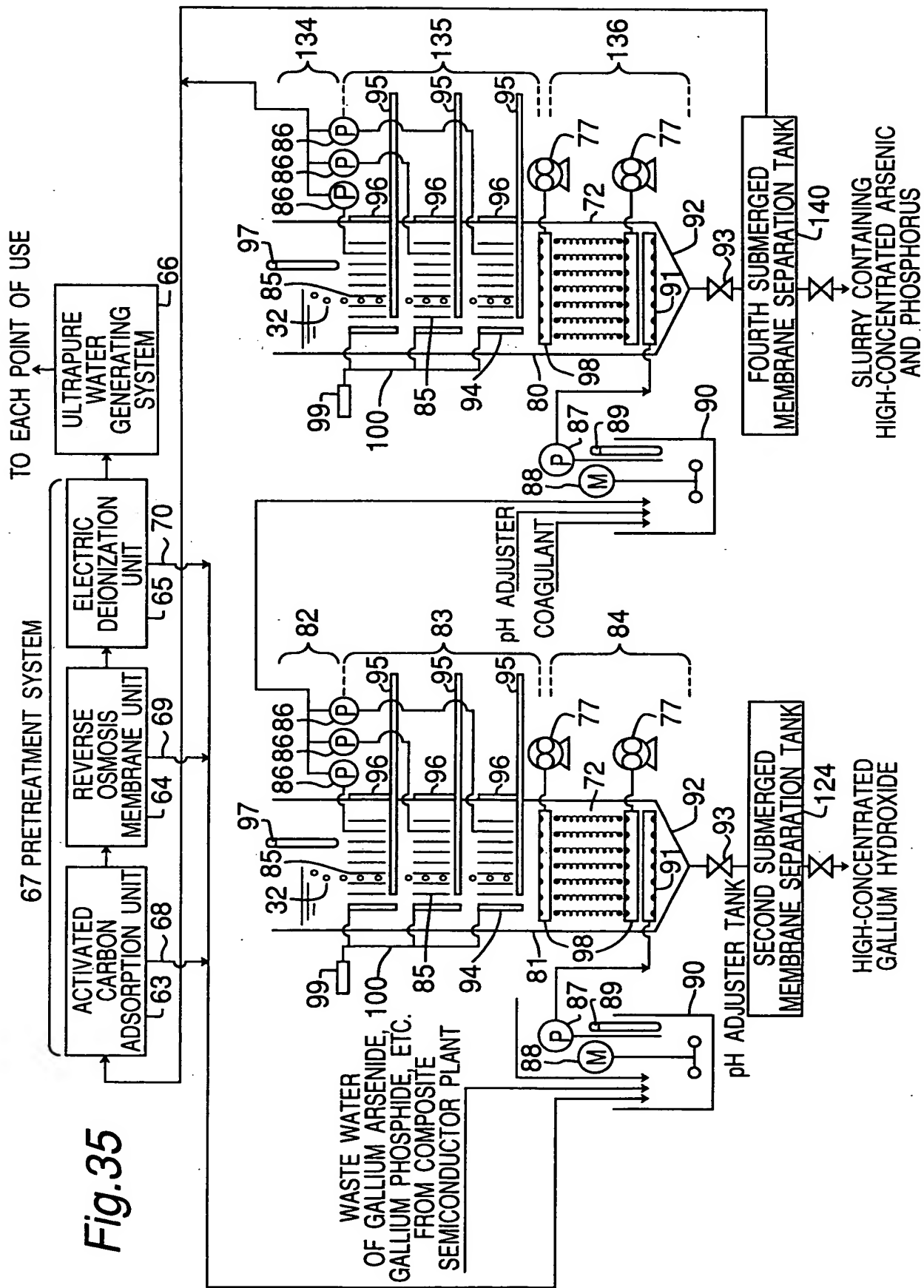


Fig.35



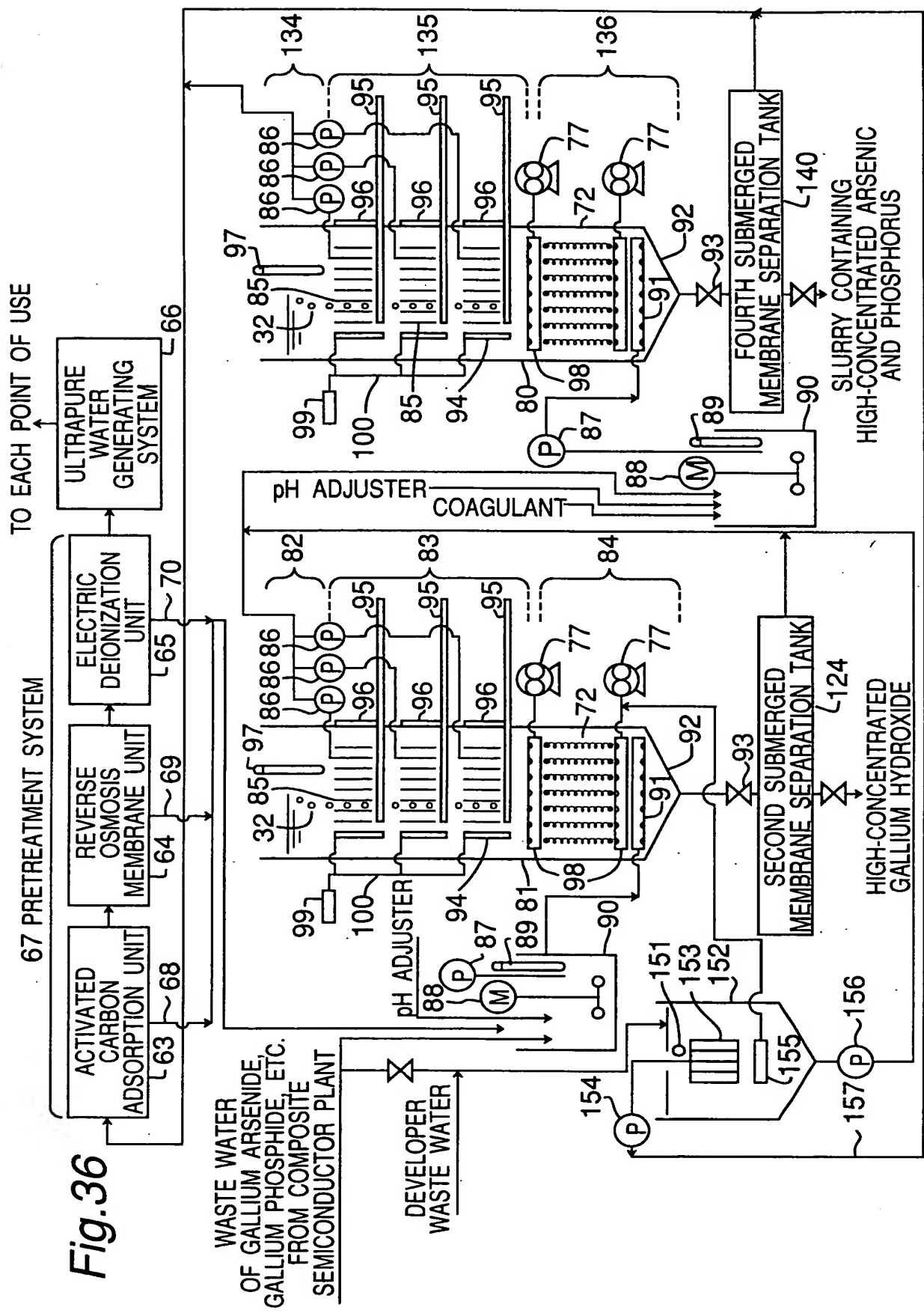
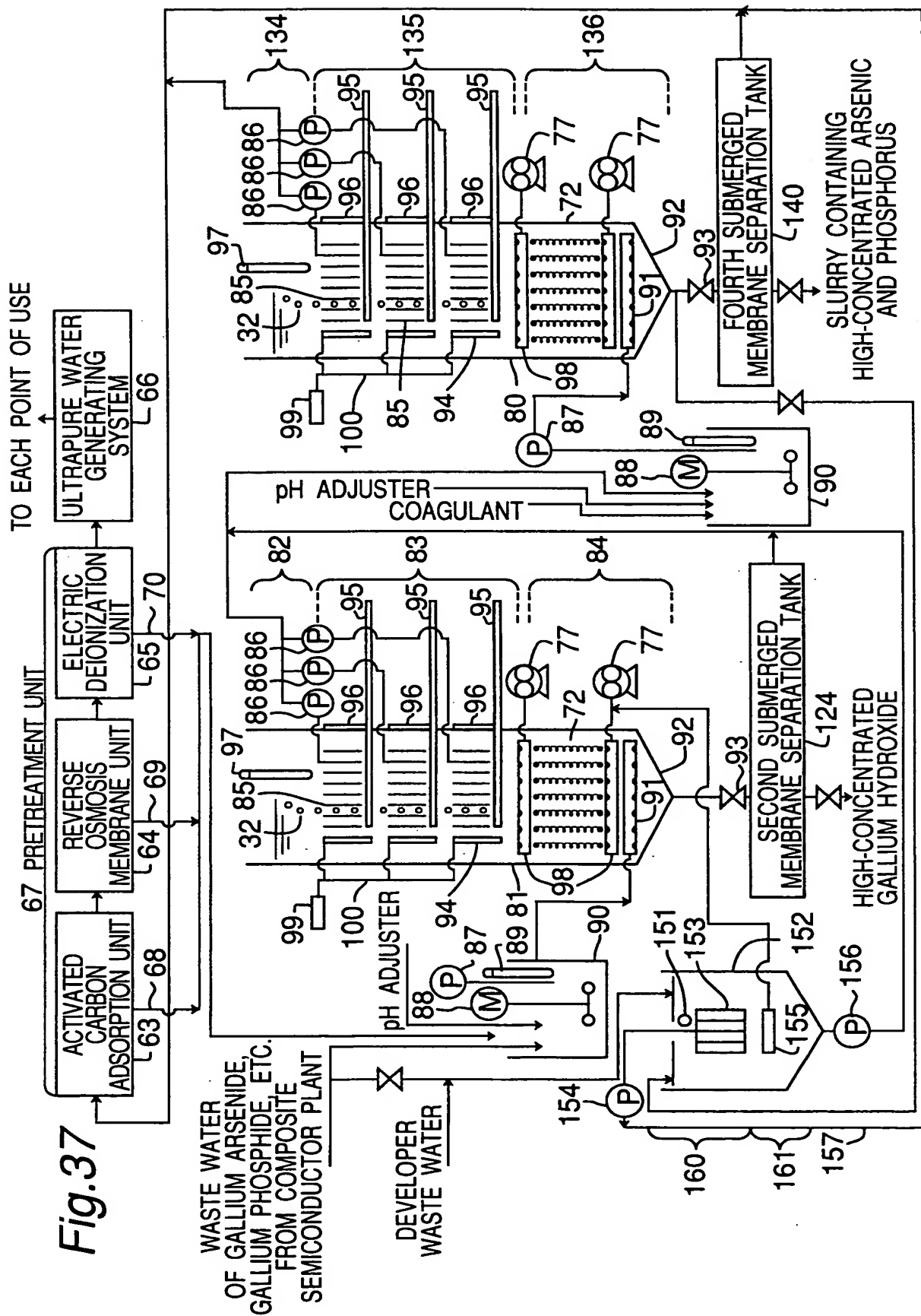


Fig.36

Fig.37



TO EACH POINT OF USE

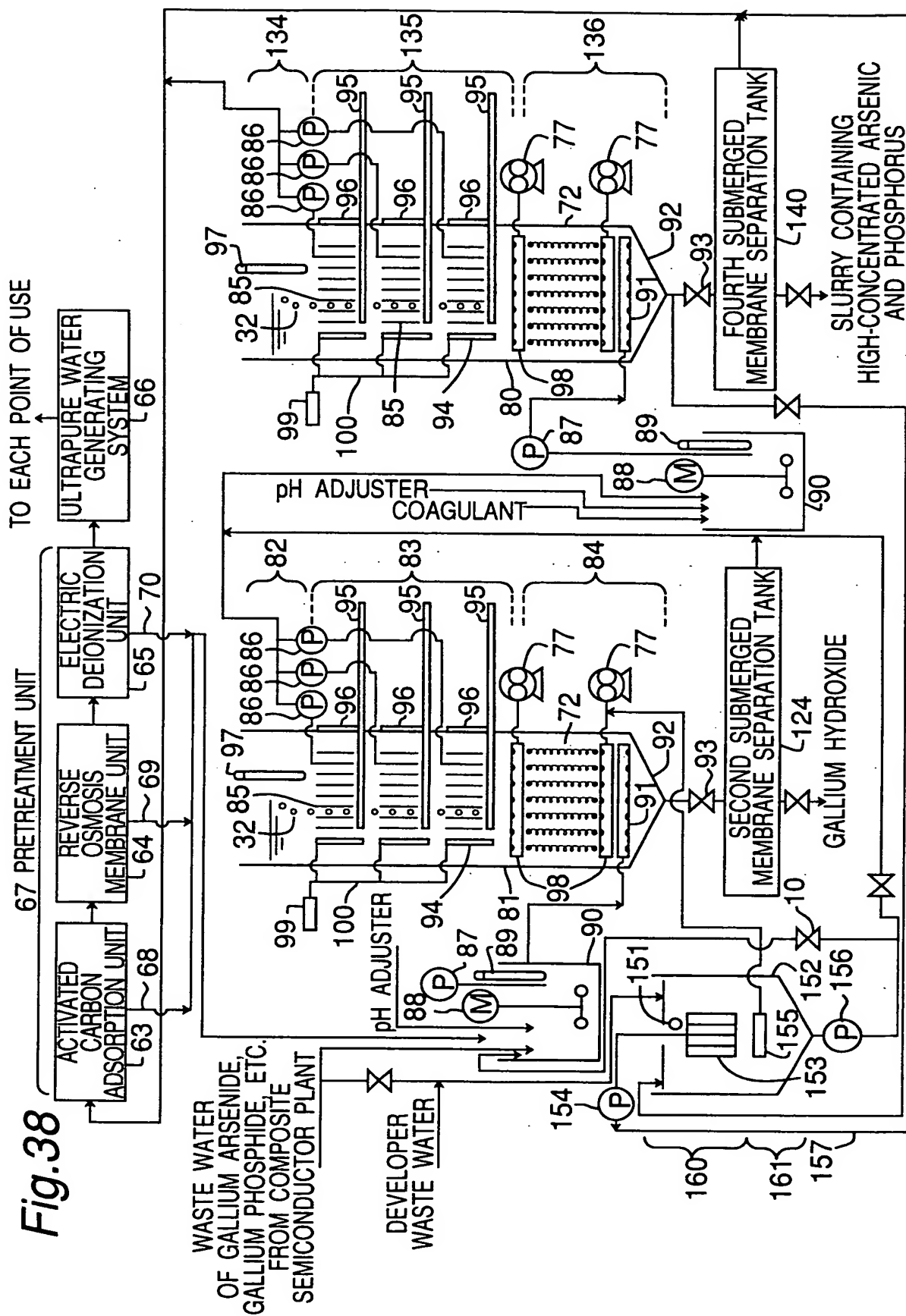


Fig.39

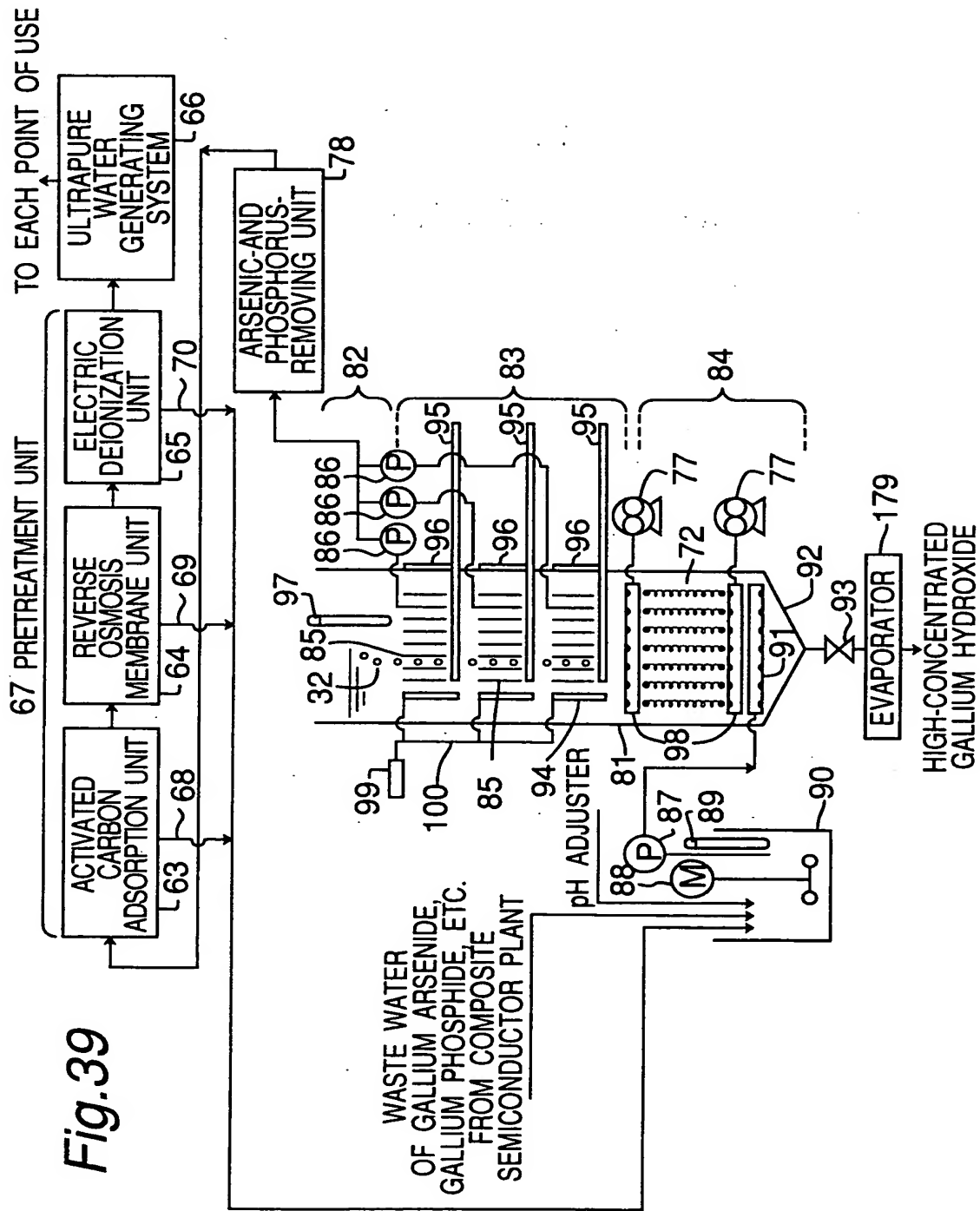


Fig. 40

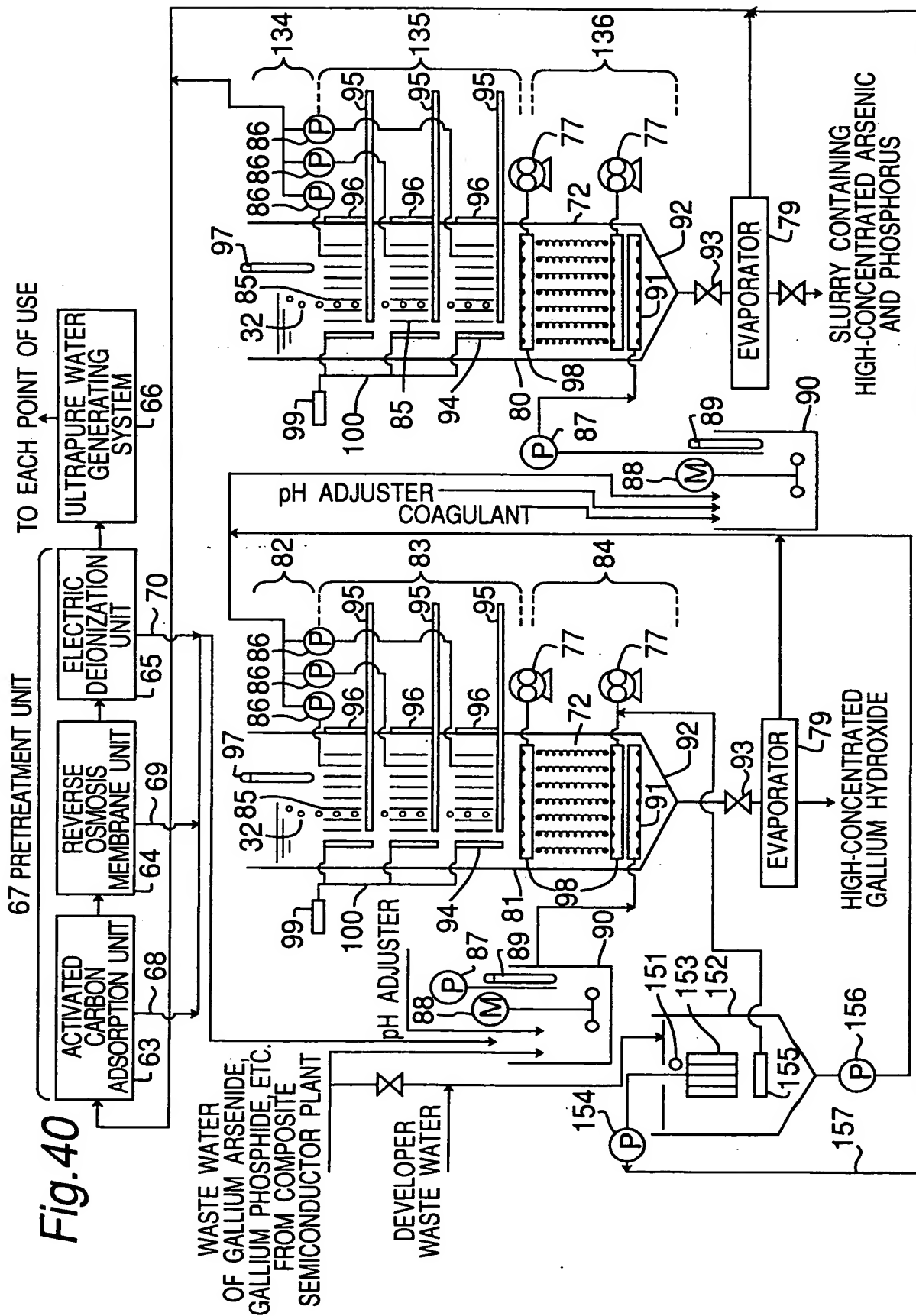


Fig. 41

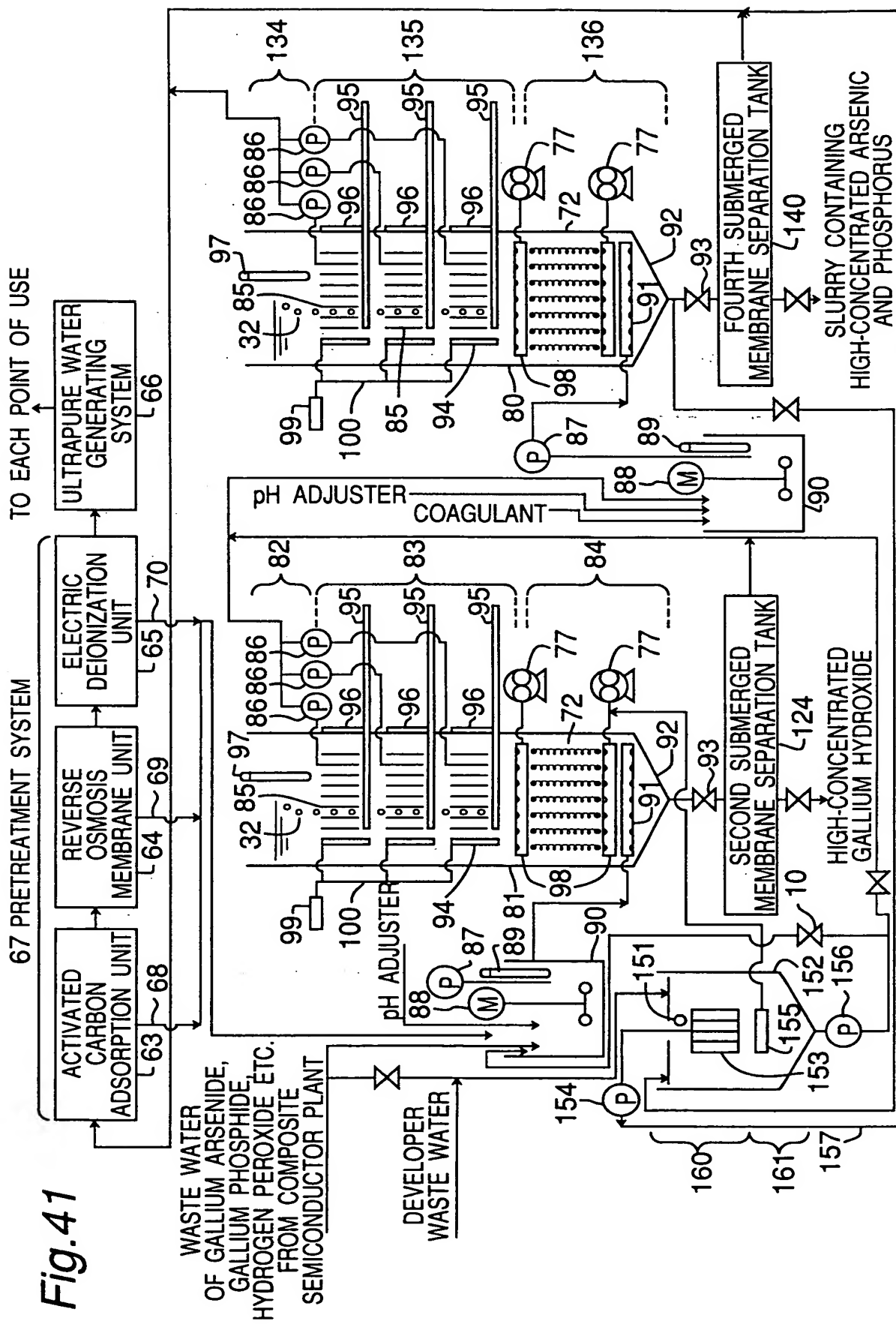


Fig. 43

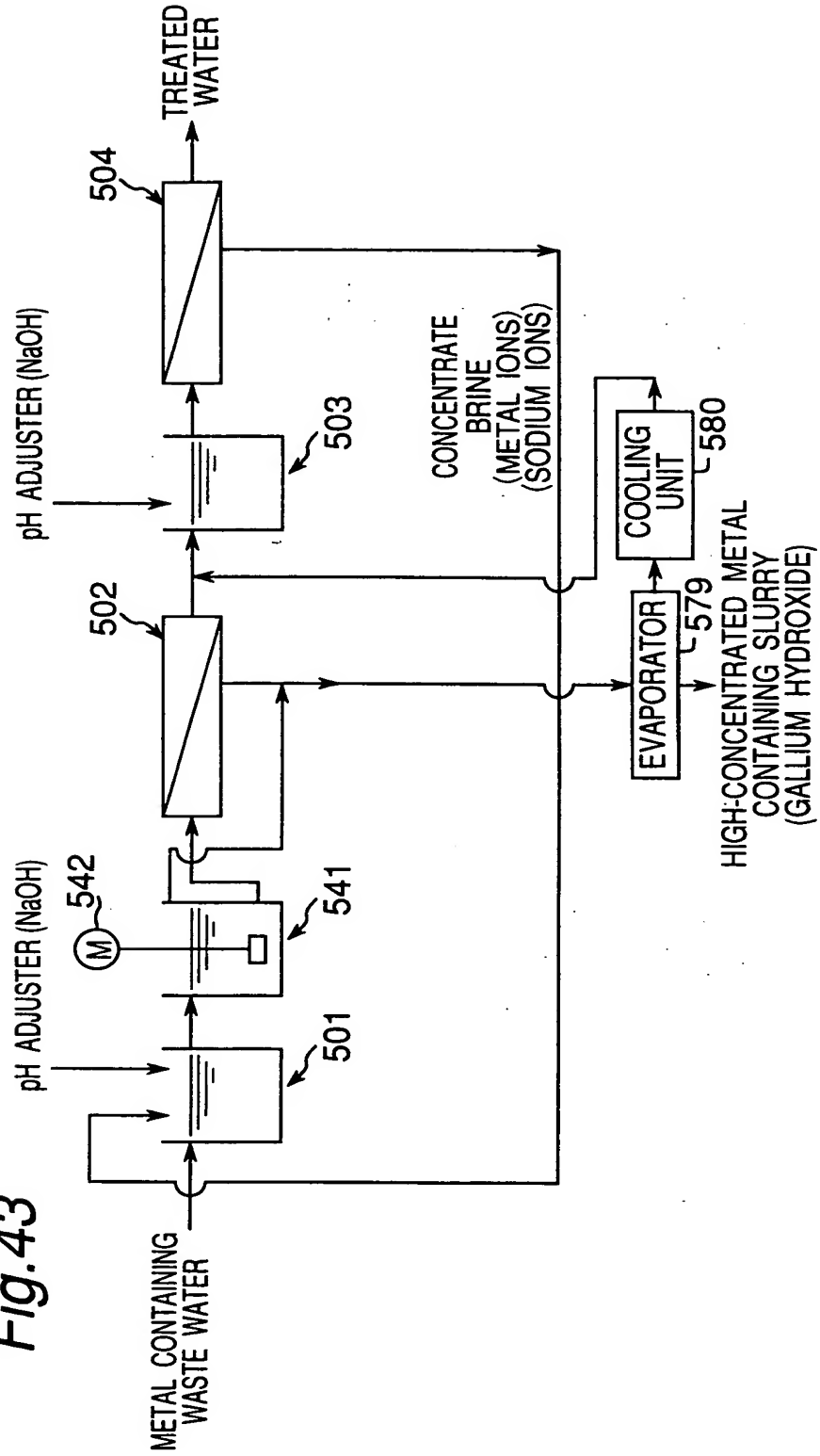


Fig. 44

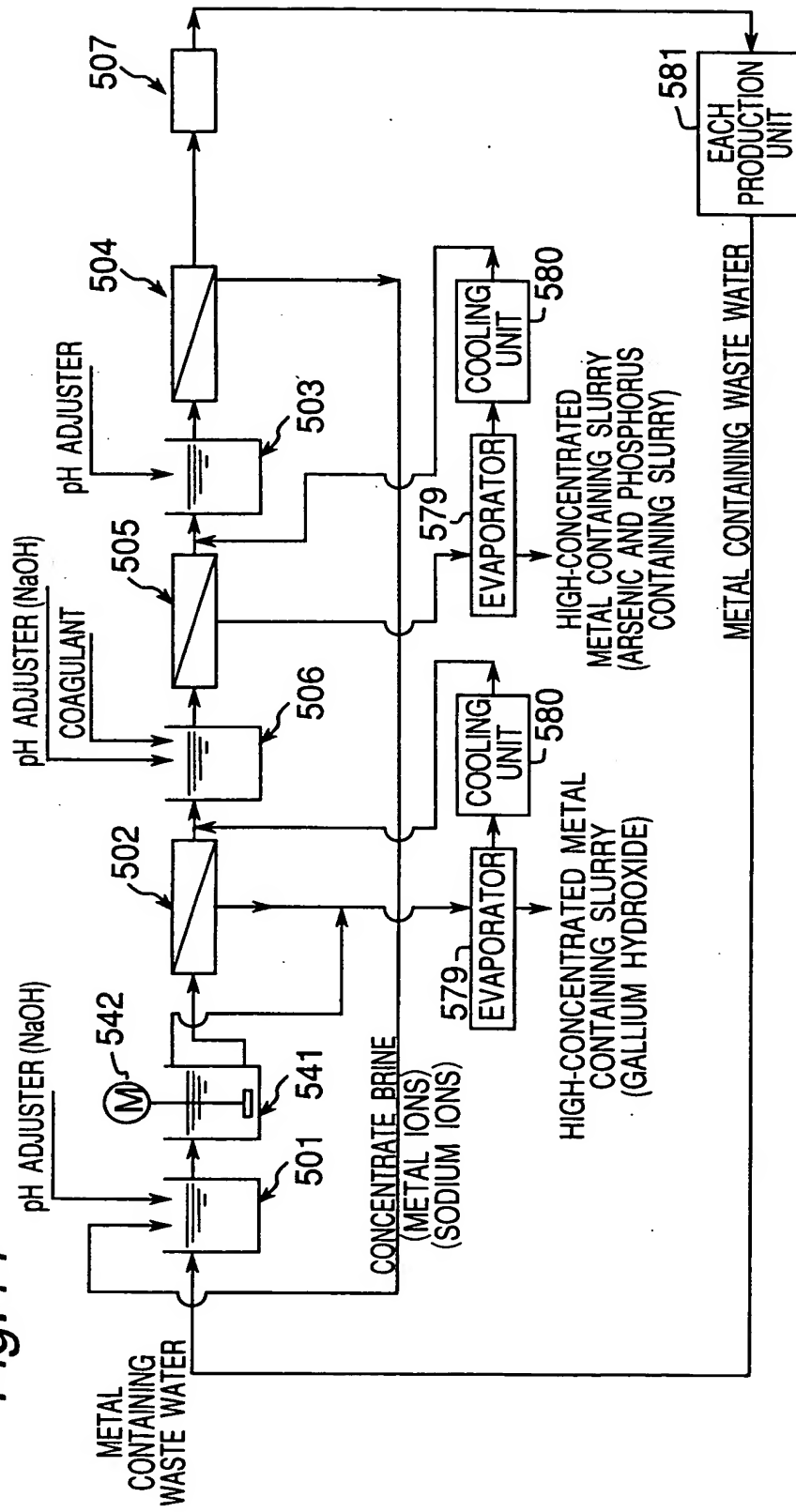


Fig.45

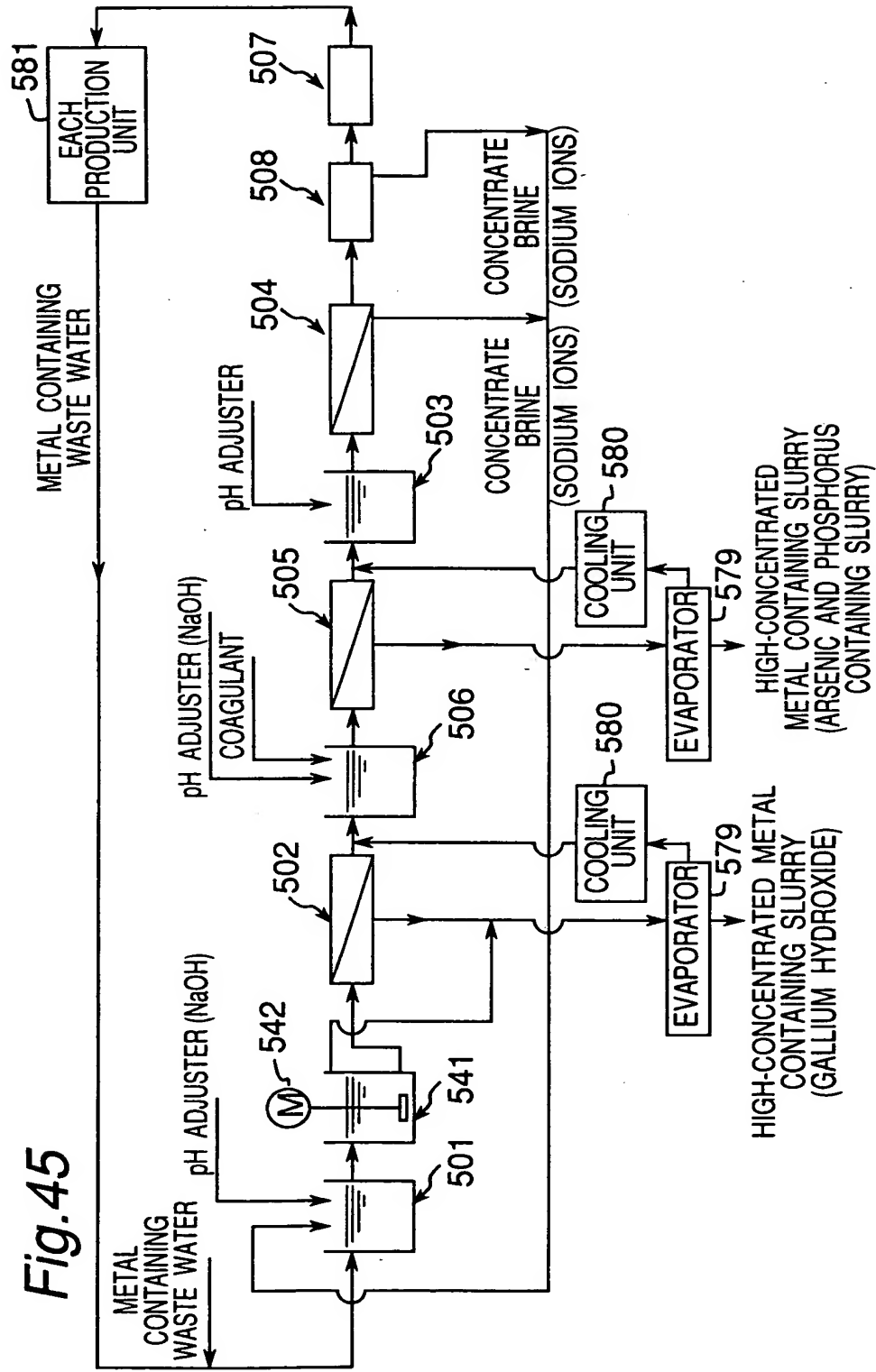


Fig.46

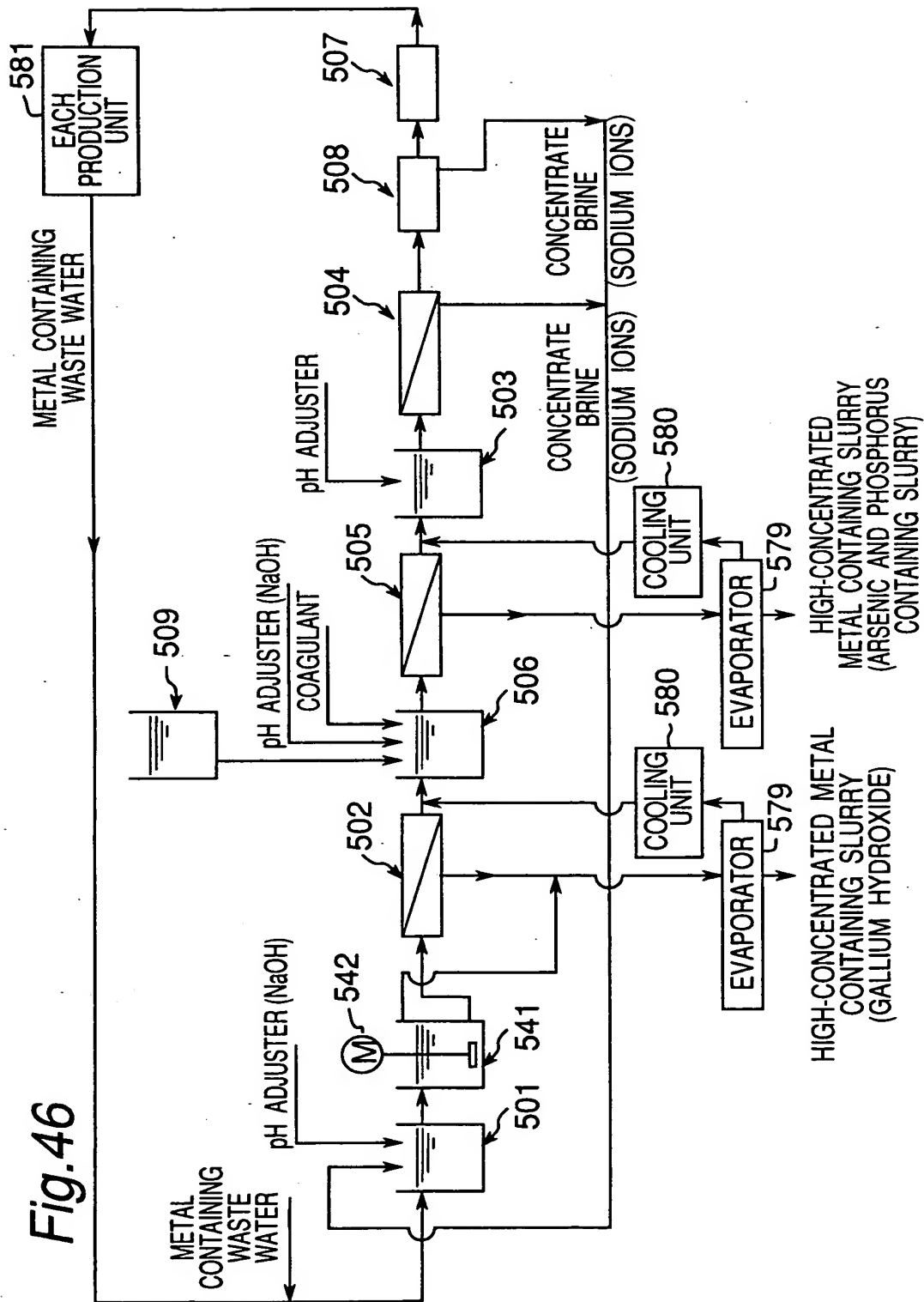


Fig.47

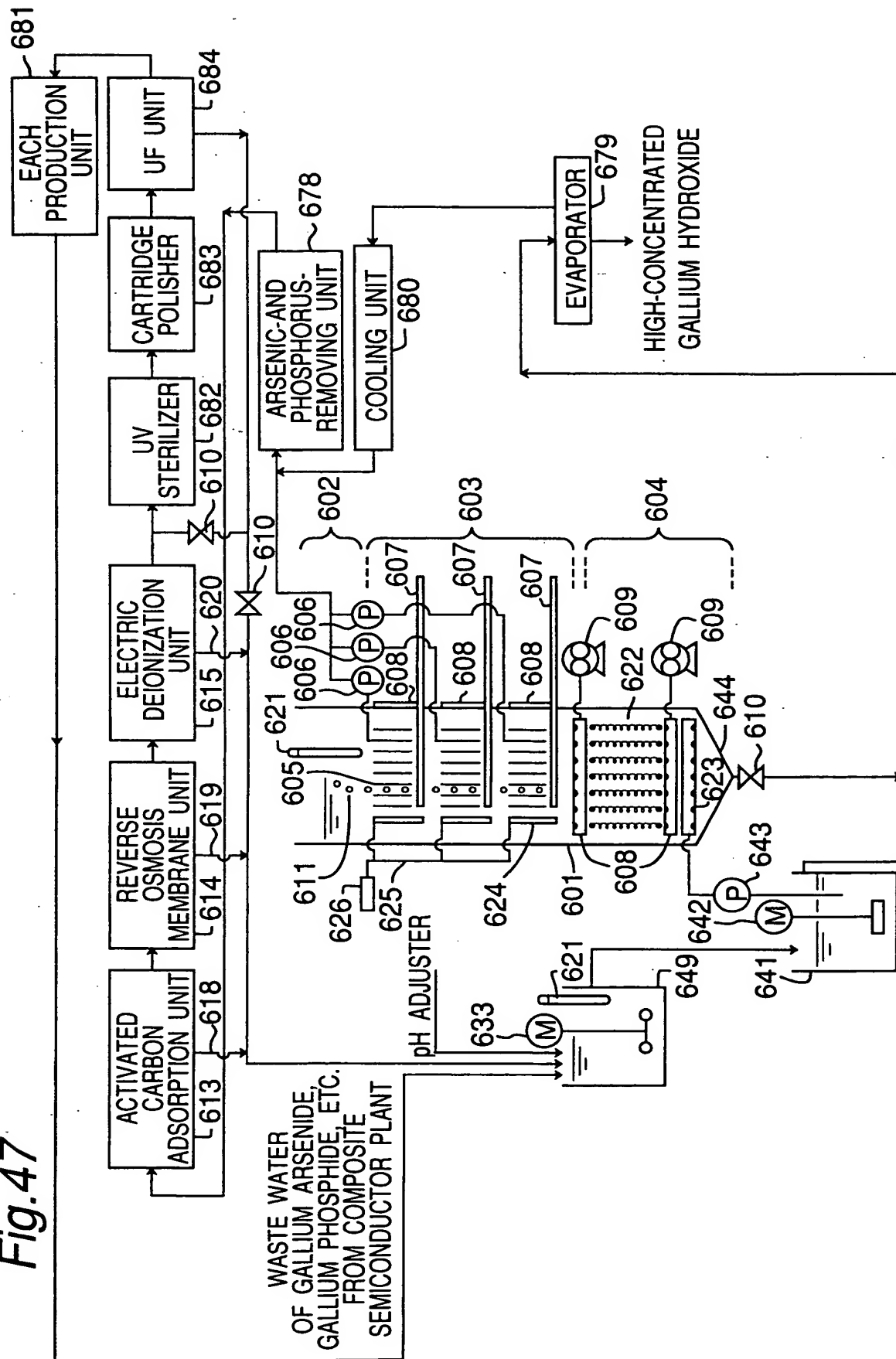


Fig. 48

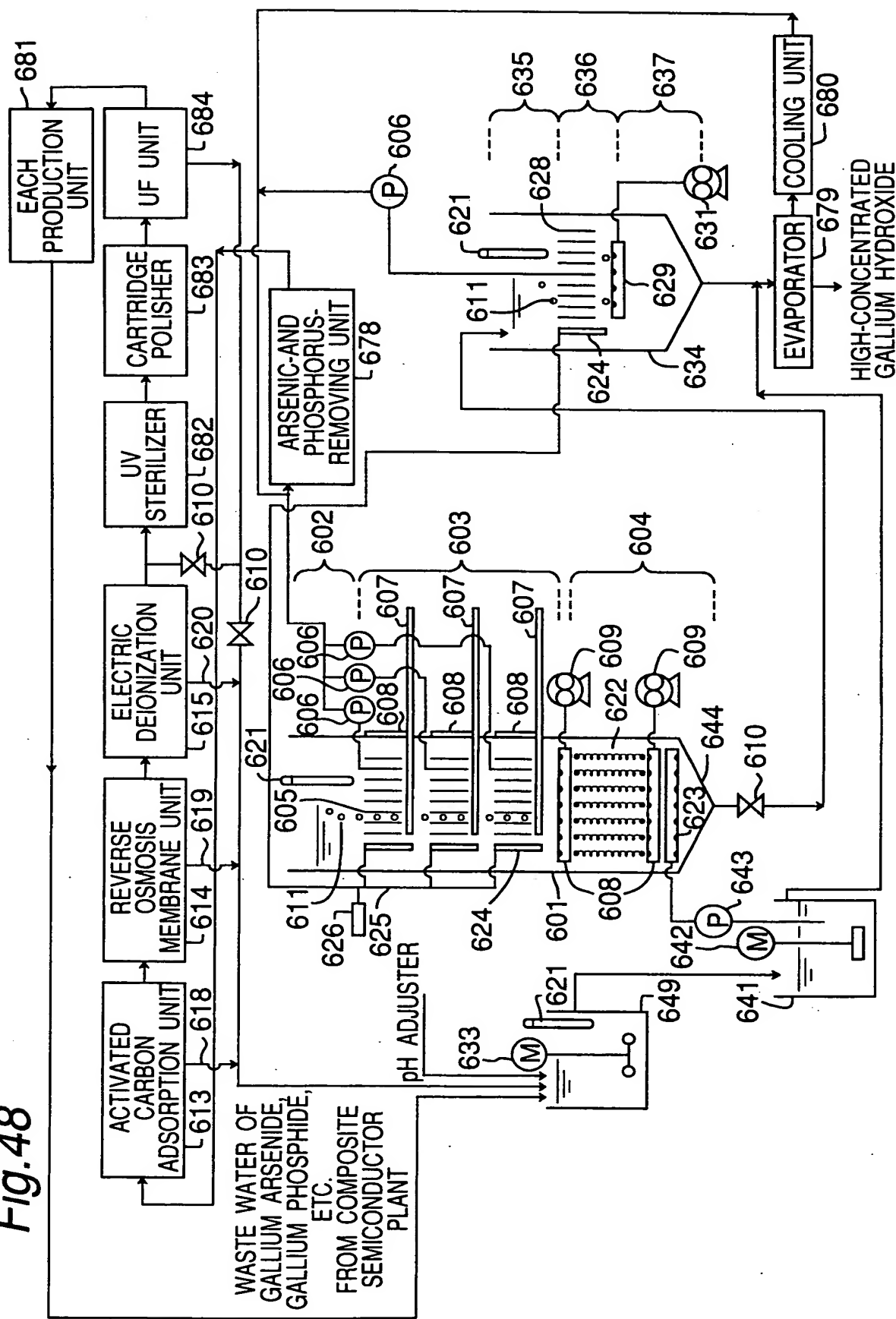


Fig. 49

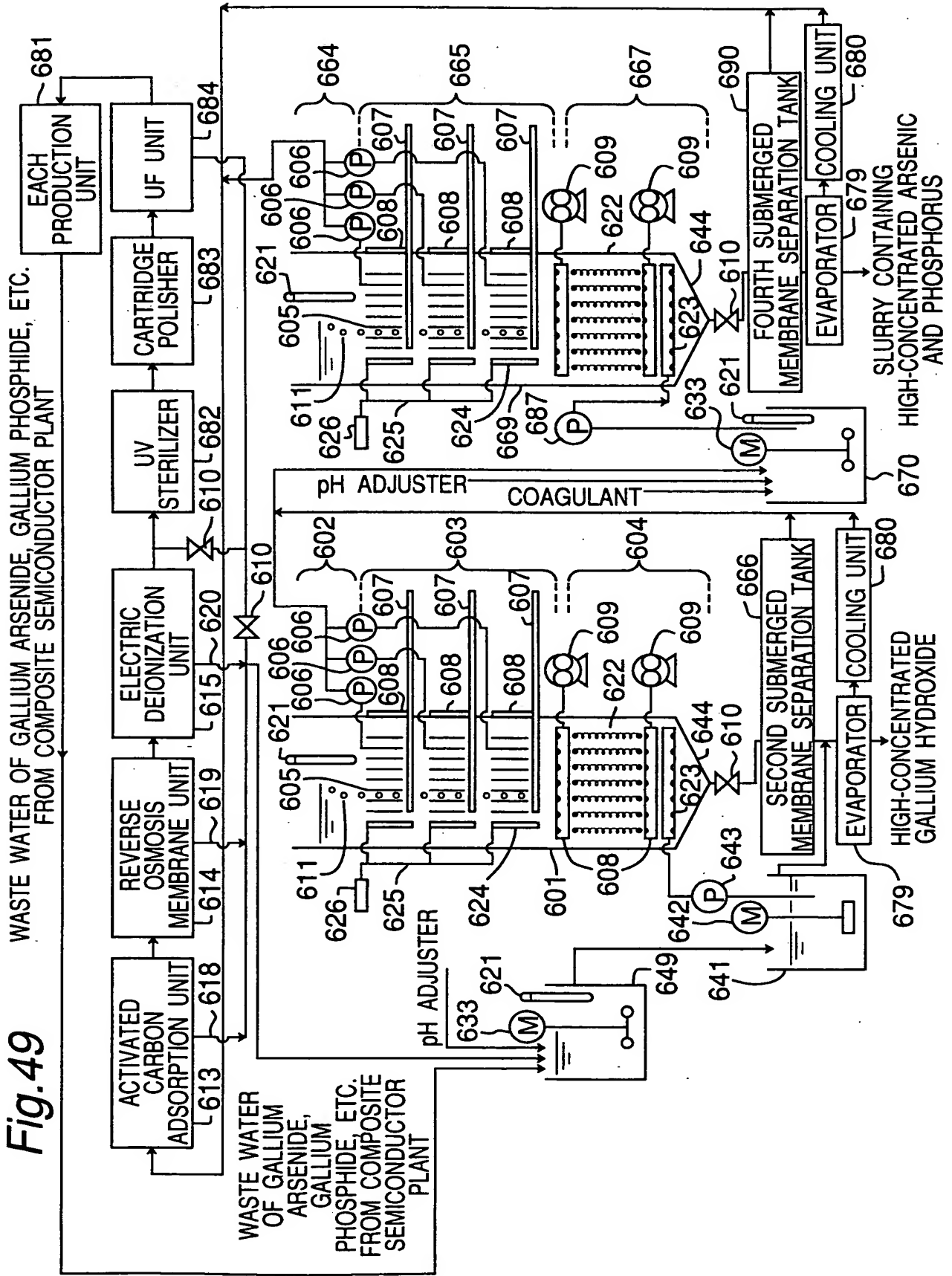


Fig. 50

The diagram illustrates a waste water treatment process for gallium arsenide, gallium phosphide, etc. from a composite semiconductor plant. The process begins with waste water entering a series of pre-treatment units: an Activated Carbon Adsorption Unit (613), a Reverse Osmosis Membrane Unit (614), an Electric Deionization Unit (615), a UV Sterilizer (682), a Cartridge Polisher (683), and a UF Unit (684). The output of the UF Unit is then fed into a production unit (681). The main treatment stage consists of two submerged membrane separation tanks (601 and 602) equipped with pH adjusters (603 and 604) and coagulant addition points (605 and 606). The tanks are connected to a series of pumps (607, 608, 609) and a fourth submerged membrane separation tank (679). The final products are high-concentrated gallium hydroxide (680) and slurry containing high-concentrated arsenic and phosphorus (680).

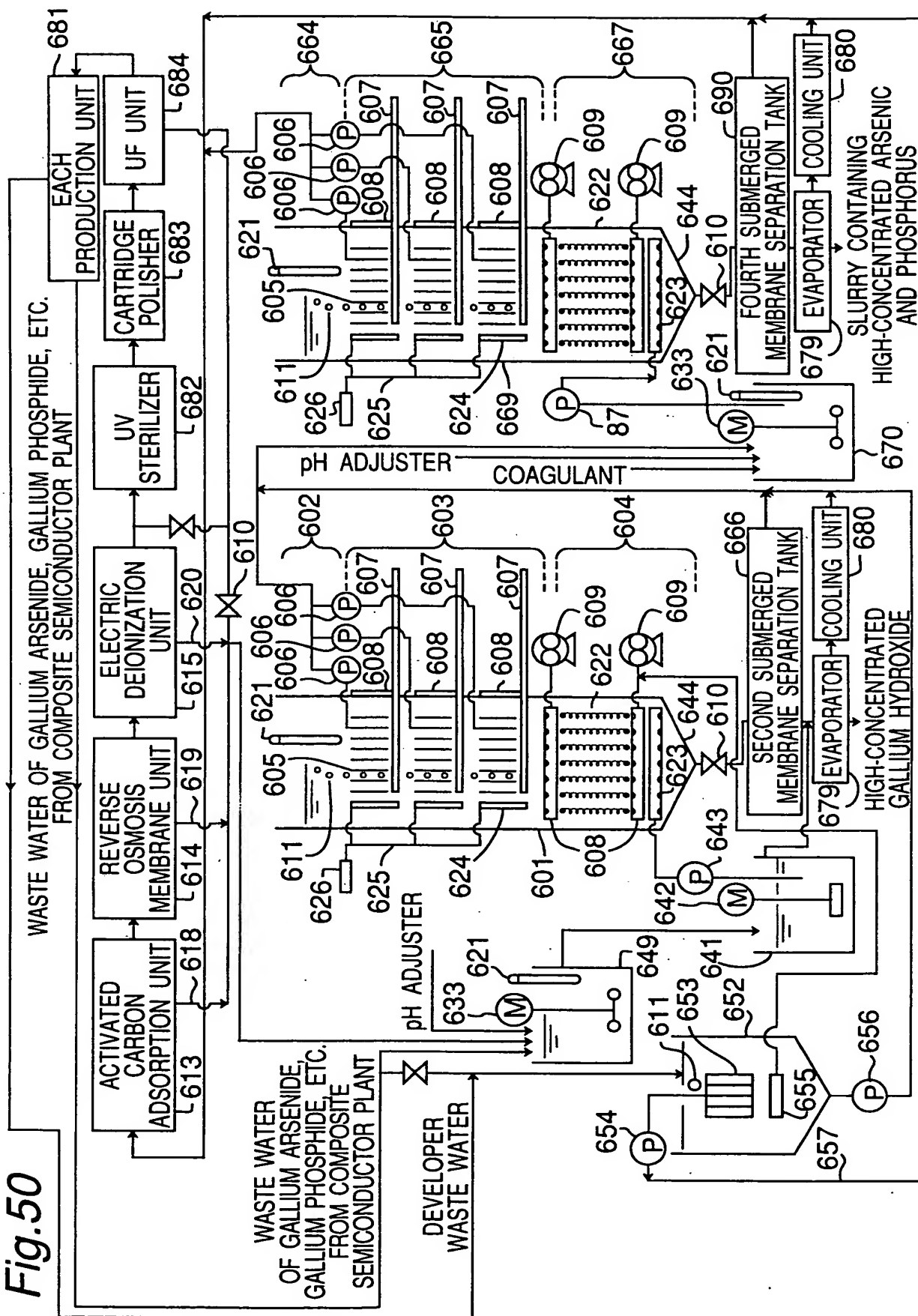
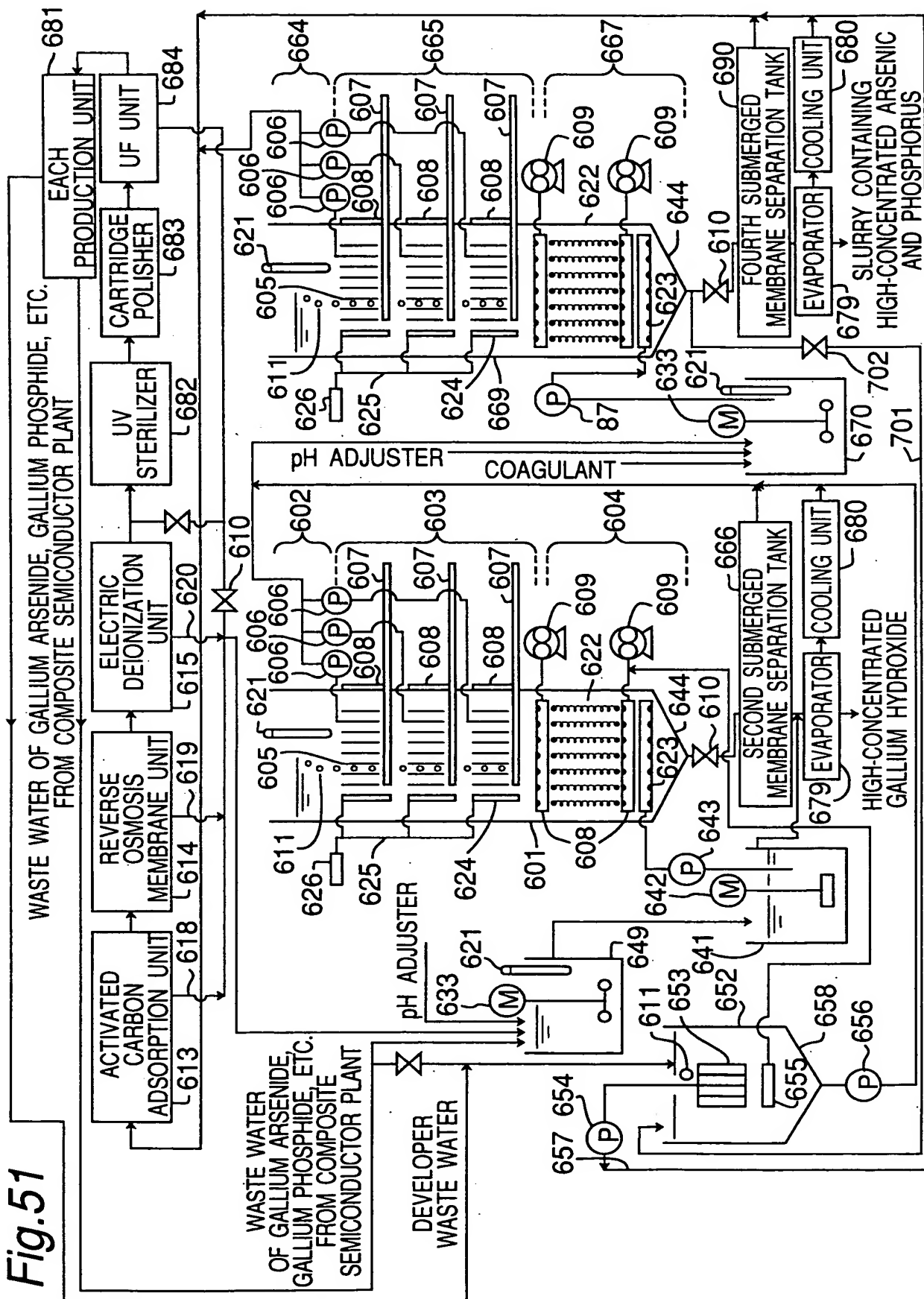


Fig.51



The diagram illustrates a semiconductor manufacturing system, specifically for gallium arsenide and gallium phosphide. The system is divided into several functional sections:

- Water Treatment Section (613-619):** This section processes waste water from a semiconductor plant. It includes an **ACTIVATED CARBON ADSORPTION UNIT** (613), a **REVERSE OSMOSIS MEMBRANE UNIT** (614), an **ELECTRIC DEIONIZATION UNIT** (615), a **UV STERILIZER** (616), and a **CARTRIDGE POLISHER** (617). The output of this section is fed into the main processing section.
- Main Processing Section (601-609):** This section is responsible for the chemical processing of the water. It includes a **CONCENTRATE BRINE, ETC.** (601), a **pH ADJUSTER** (602), and an **ARSENIC-AND-PHOSPHORUS-REMOVING UNIT** (603). The output of this section is fed into an **EVAPORATOR** (604), which produces **HIGH-CONCENTRATED GALLIUM HYDROXIDE**.
- Waste Water Section (621-625):** This section handles waste water from the semiconductor plant. It includes a **WASTE WATER OF GALLIUM ARSENIDE, GALLIUM PHOSPHIDE, ETC. FROM COMPOSITE SEMICONDUCTOR PLANT** (621), a **CONCENTRATE BRINE, ETC.** (622), a **pH ADJUSTER** (623), and an **ARSENIC-AND-PHOSPHORUS-REMOVING UNIT** (624). The output of this section is fed into the main processing section.
- Control and Monitoring Section (681-684):** This section includes a **PRODUCTION UNIT** (681) and a **UF UNIT** (684), which are used to control and monitor the entire process.

The diagram shows the flow of materials and the interconnections between these various units, highlighting the complexity of the semiconductor manufacturing process.

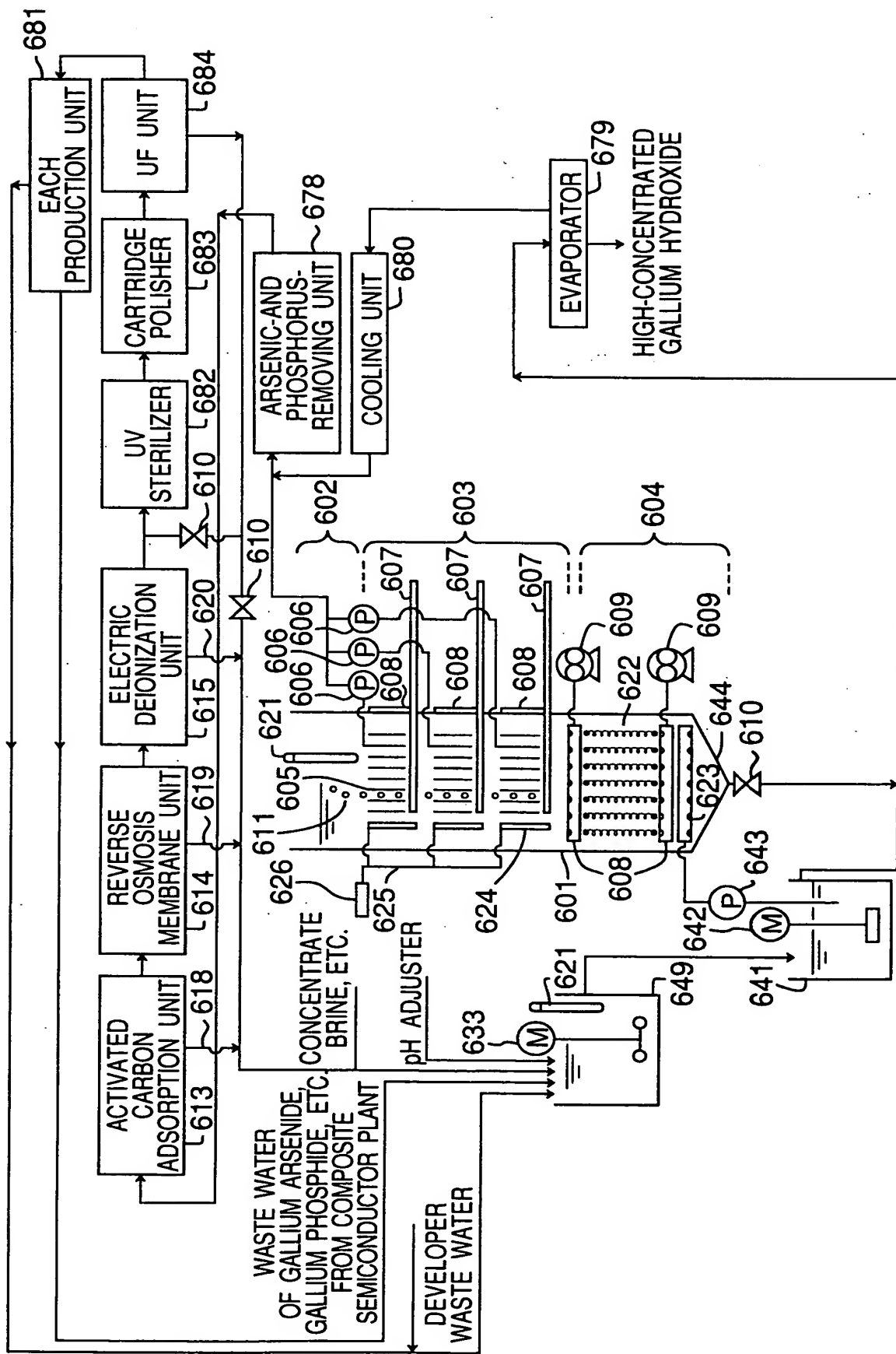


Fig. 54

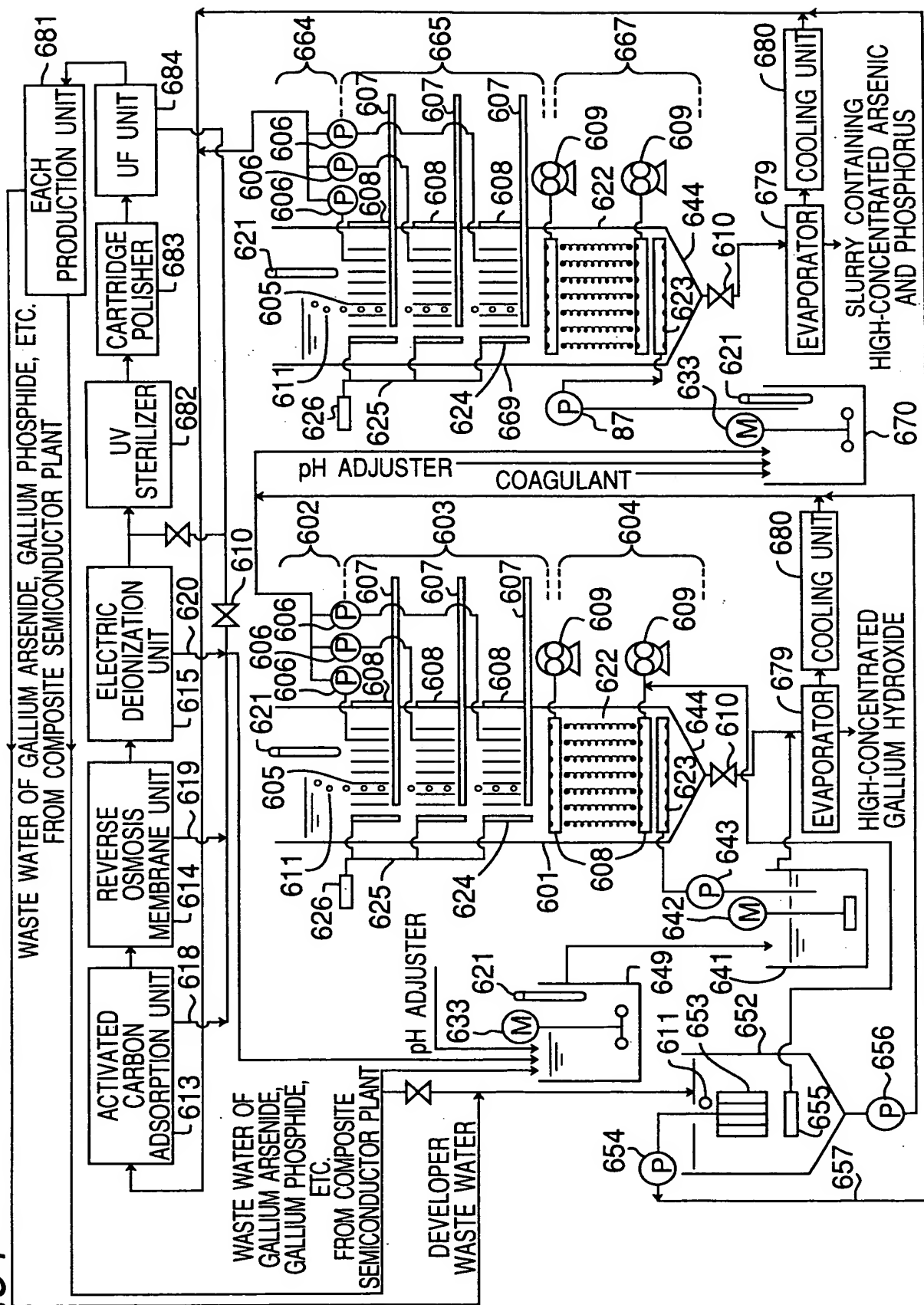
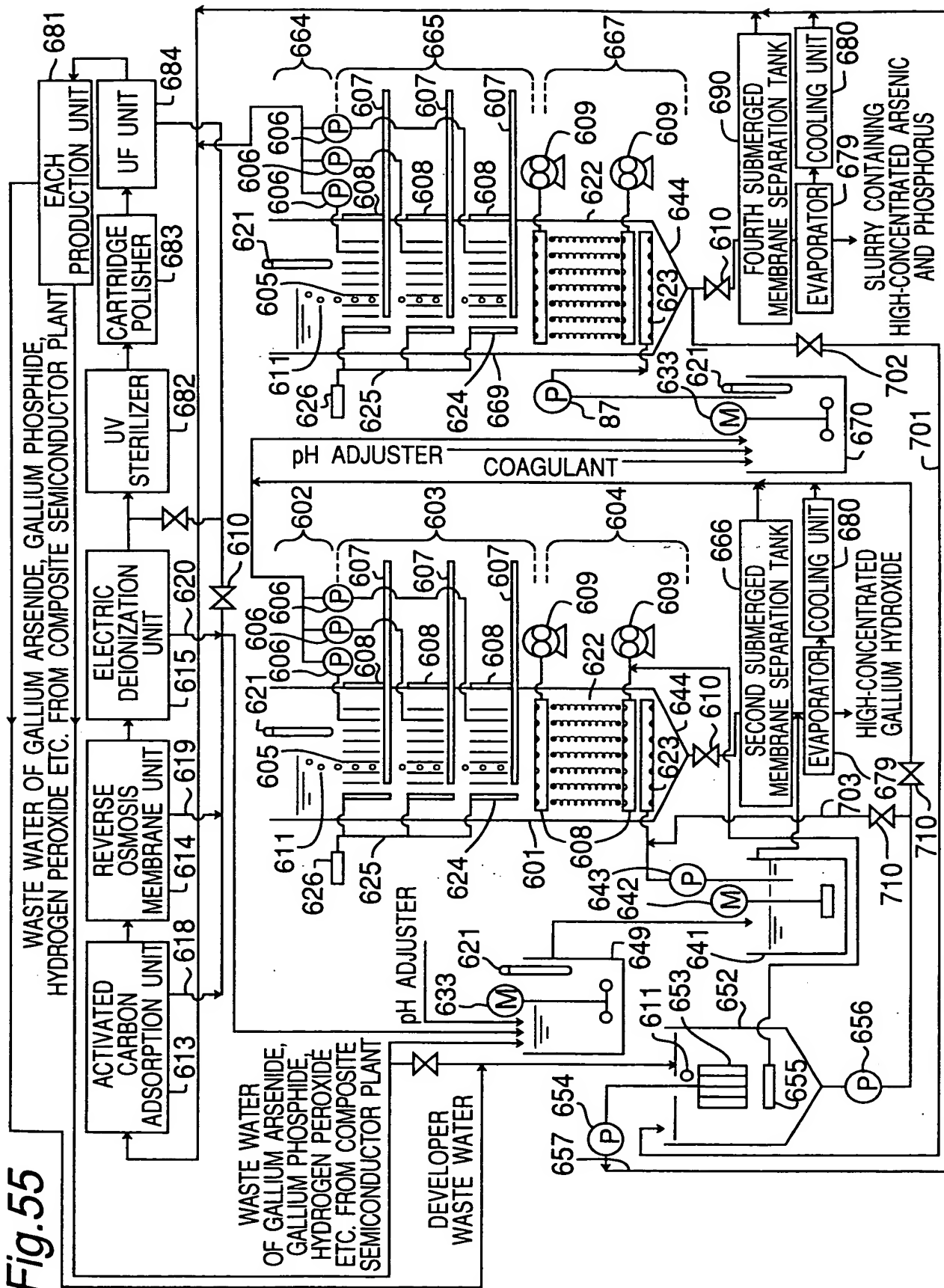


Fig.55



WHEN CONCENTRATIONS OF GALLIUM AND ARSENIC ARE NORMAL CONCENTRATIONS

[illegible]

WHEN CONCENTRATIONS OF GALLIUM AND ARSENIC ARE LOW CONCENTRATIONS

[illegible]

Fig.57

STRUCTURE OF FOAM SEPARATION TANK

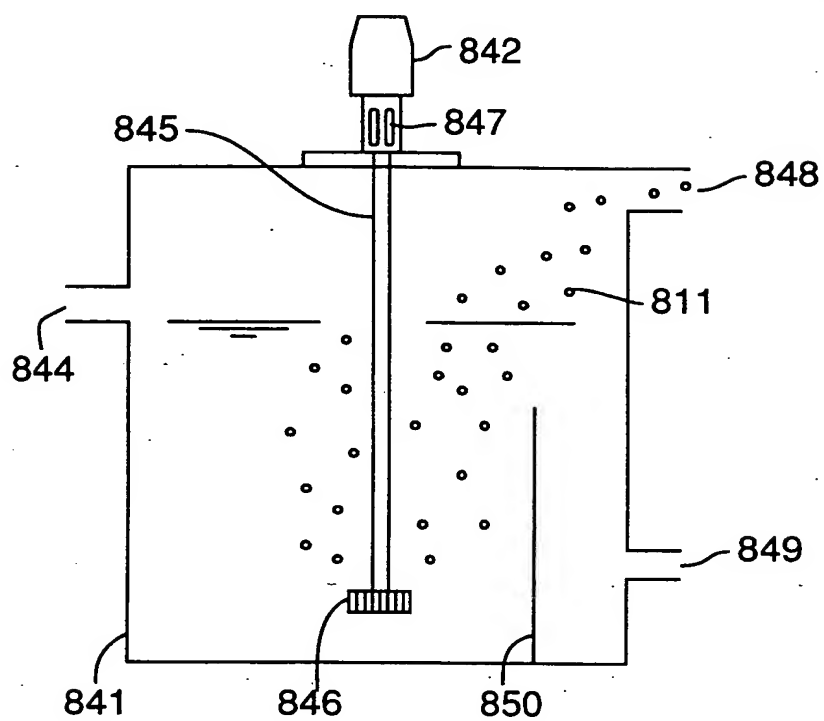


Fig. 58

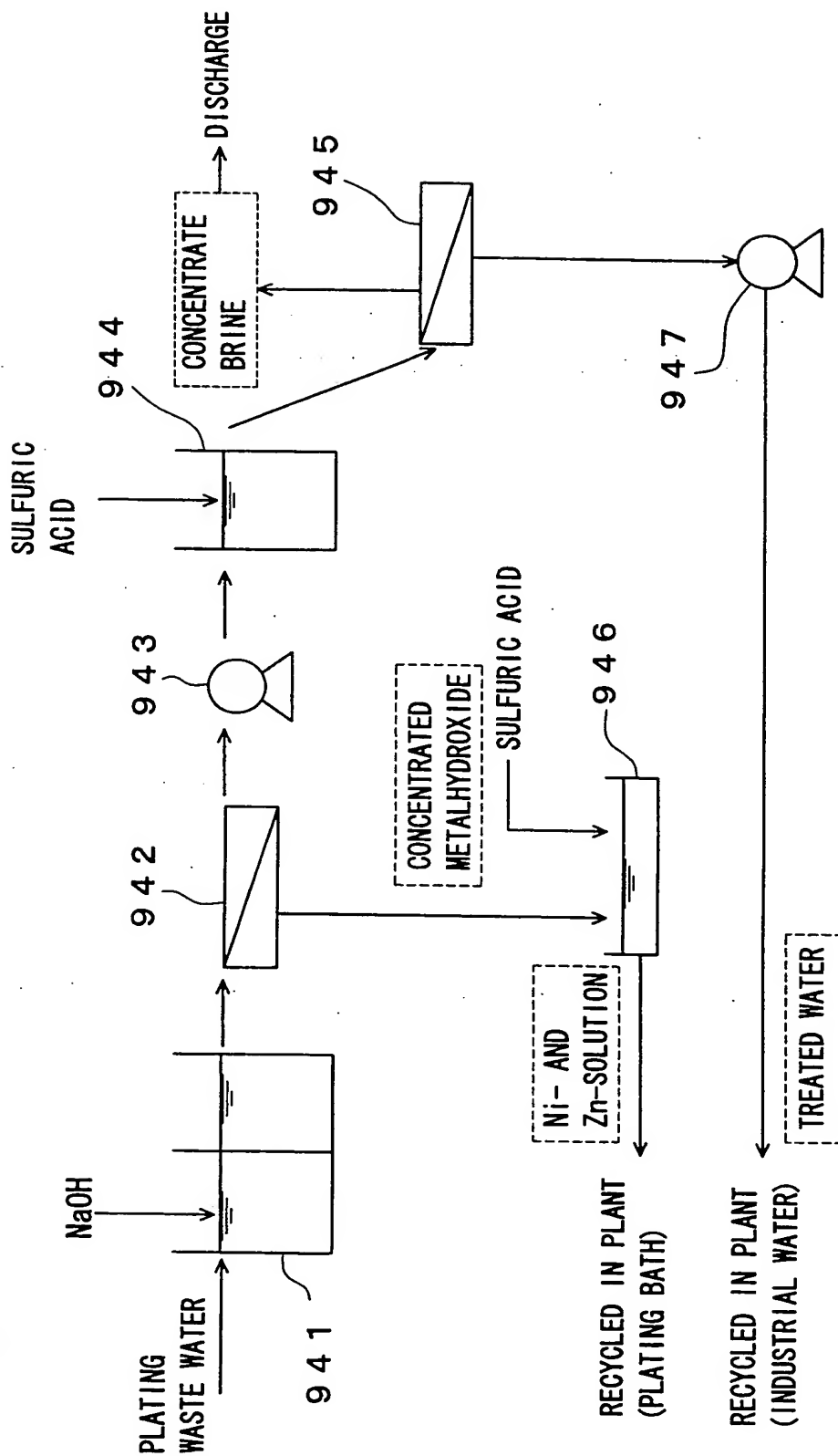


Fig. 59

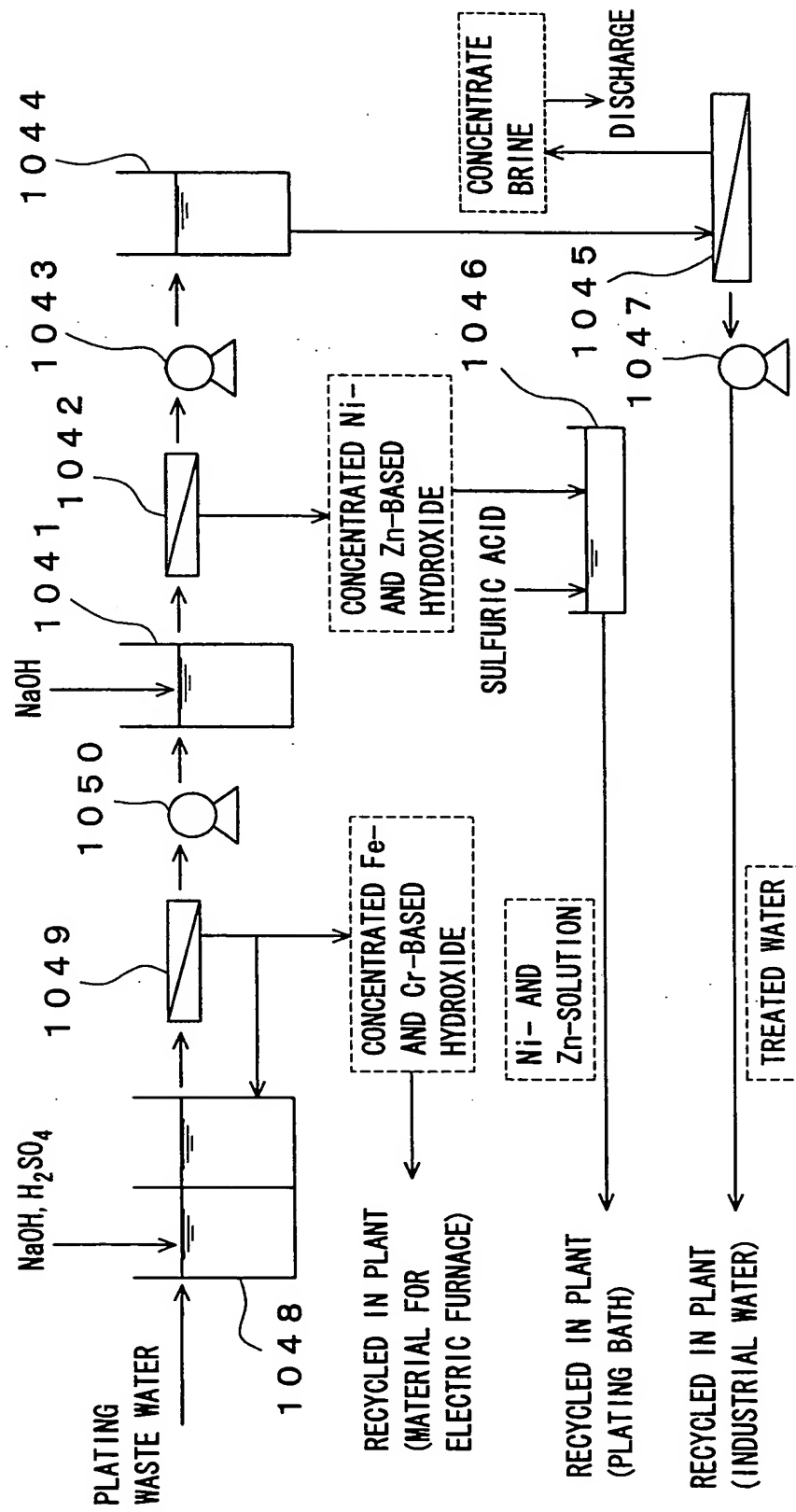


Fig. 60

